How to Deliver Oodles and Oodles of Current to HEP Detectors in High Radiation and Magnetic Fields?

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Yale University

KEK Seminar

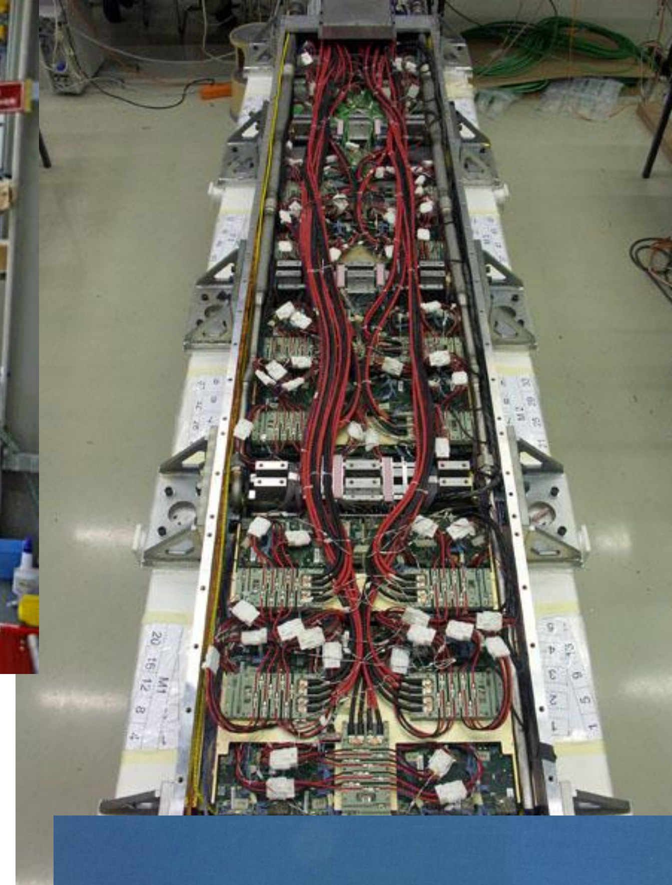
June 14, 2010

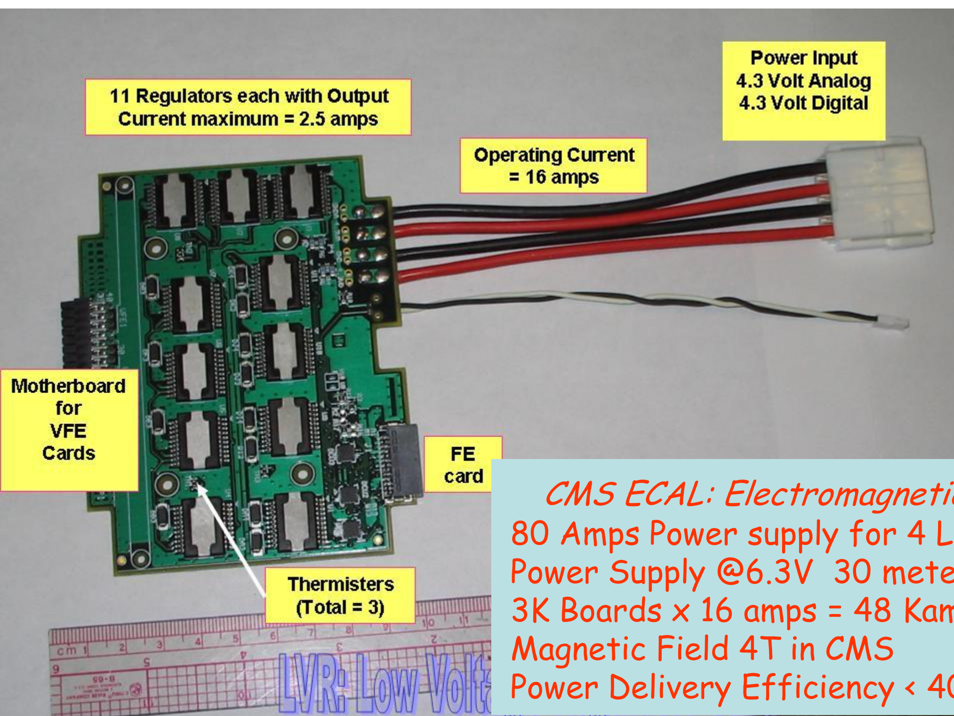
1 Oodle = 10,000 amps

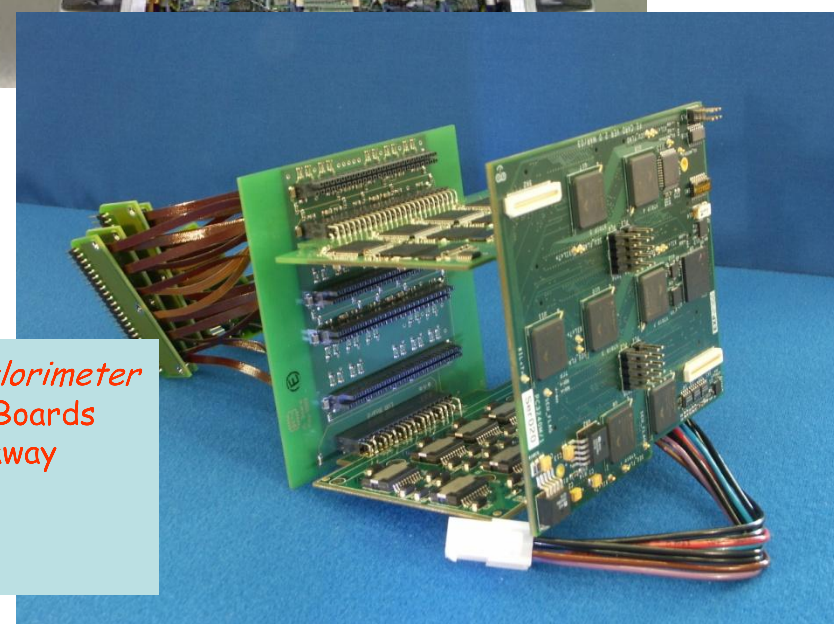
Agenda

- Power efficiency issues / problems CMS-ECAL Example
- What can we do?
- A commercial Rad Hard Converter - EN5360 can still buy it
- Buck Converter
- Plug in cards with Air Coil
- Noise Test with Detectors
- Magnetic Field 7 T – no effect
- Why need Thin Oxide
- LDMOS: Radiation Test Results
- GaN Wide band Gap materials
- Converters 36V – 1.2V & 48V -1.8
- Industry Developments & Market Trends
- Power Supply Current Reduction
- Remarks

Collaborators:
Yale University: Keith Baker, Hunter Smith







CMS ECAL: Electromagnetic Calorimeter

80 Amps Power supply for 4 LVR Boards
Power Supply @6.3V 30 meters away
3K Boards x 16 amps = 48 Kamps
Magnetic Field 4T in CMS
Power Delivery Efficiency < 40 %

CMS ECAL: 5 Oodles (50 Kamps) .

Power Supply output	= 315 KW
Power loss in Leads to SM	= 100 KW
Power loss in Regulator Card	= 90 KW
Power Delivered @ 2.5 V	= 125 KW

\# of Power Supplies ~ 700
\# of ST LDO Chips = 35 K LHC Radiation Hard made by ST Microelectronics
\# of LVR Cards = 3.1 K.

Yale: Designed, built, burn-in and Tested.

Power Supply
6.3 V

64 Amps

30 m

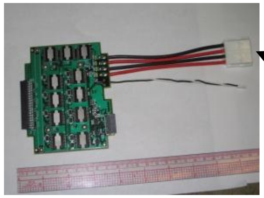
Vdrop = 2V
Pd = 128 W

50 mm^2 (AWG 00)

2x16 mm^2 (AWG 6)

1 to 3 m

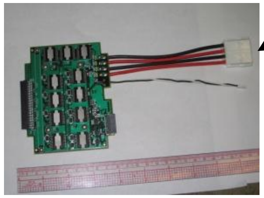
SM: Super Module



4.3 V

Junction Box

2.5V
64 amps
160 W



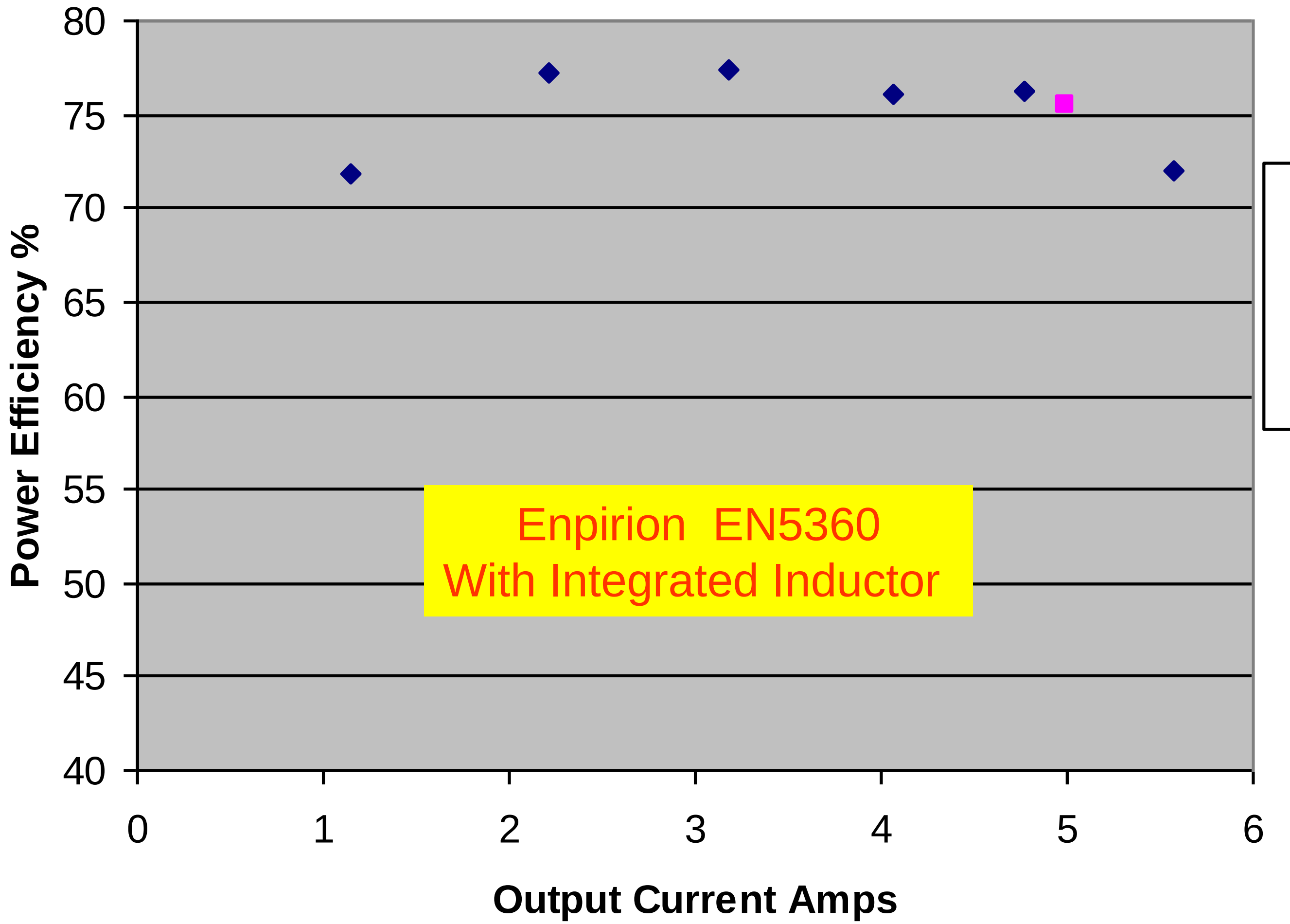
4 LVR Boards

Power Delivery Efficiency = 40%
NOT INCLUDED
1. Power Supply efficiency
2. Water cooling
3. Removal of Waste heat
4. Air Conditioning

What can we do?

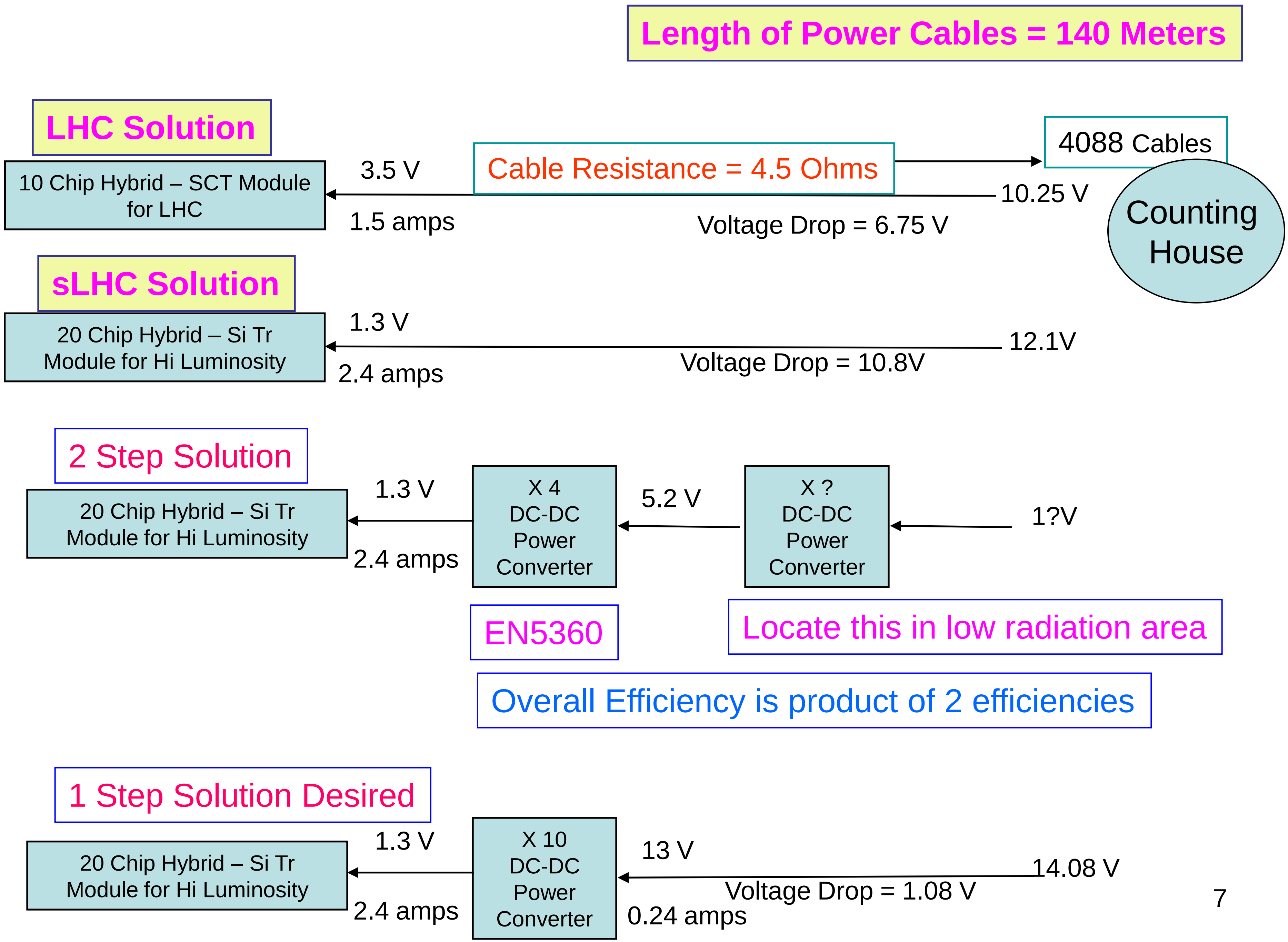
- Is there a better way to distribute power ?
- High Radiation
- Magnetic Field 4 T
- Load ~1 V Oodles of current
- Feed High Voltage and Convert - *like AC power transmission*
- Commercial Technologies – *No Custom ASIC Chips*
- Learn from Semiconductor Industry
- Use Company Evaluation Boards for

Buck Regulator Efficiency after 100 Mrad dosage



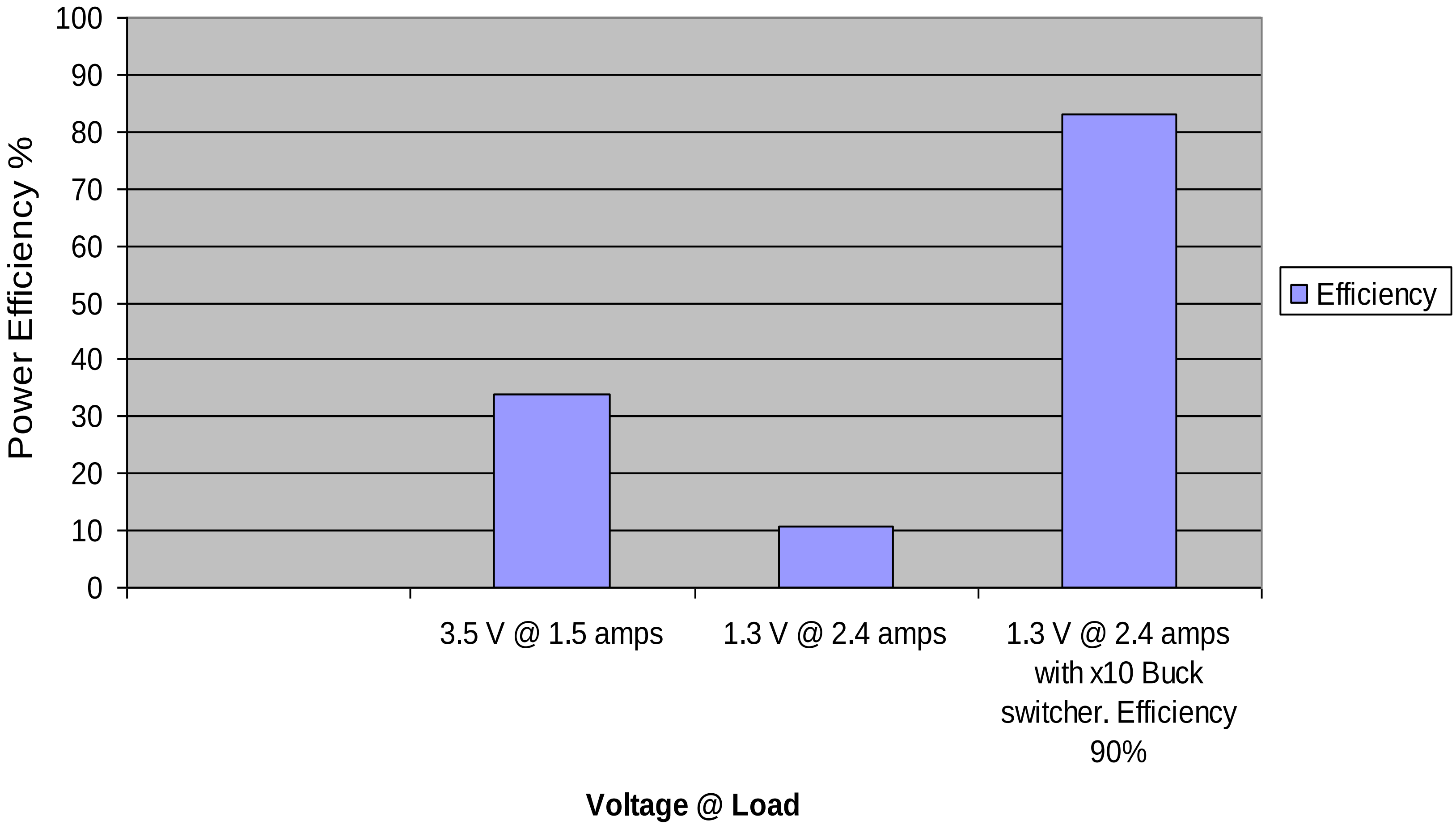
Found out at Power Technology conference 0.25 µm Lithography

- Irradiated Stopped on St. Valentines Day 2007
- We reported @ TWEPP 2008 - IHP was foundry for EN5360


Length of Power Cables = 140 Meters
LHC Solution
10 Chip Hybrid – SCT Module for LHC
3.5 V
1.5 amps
Cable Resistance = 4.5 Ohms
4088 Cables
10.25 V
Voltage Drop = 6.75 V
Counting House
sLHC Solution
20 Chip Hybrid – Si Tr Module for Hi Luminosity
1.3 V
2.4 amps
12.1V
Voltage Drop = 10.8V
2 Step Solution
20 Chip Hybrid – Si Tr Module for Hi Luminosity
1.3 V
2.4 amps
X 4 DC-DC Power Converter
5.2 V
X ? DC-DC Power Converter
1?V
EN5360
Locate this in low radiation area
Overall Efficiency is product of 2 efficiencies
1 Step Solution Desired
20 Chip Hybrid – Si Tr Module for Hi Luminosity
1.3 V
2.4 amps
X 10 DC-DC Power Converter
13 V
0.24 amps
14.08 V
Voltage Drop = 1.08 V

Power Delivery with Existing SCT Cables (total = 4088)

Resistance = 4. 5 Ohms



Type of High to Low Voltage Converters without transformers

❖ Charge pumps

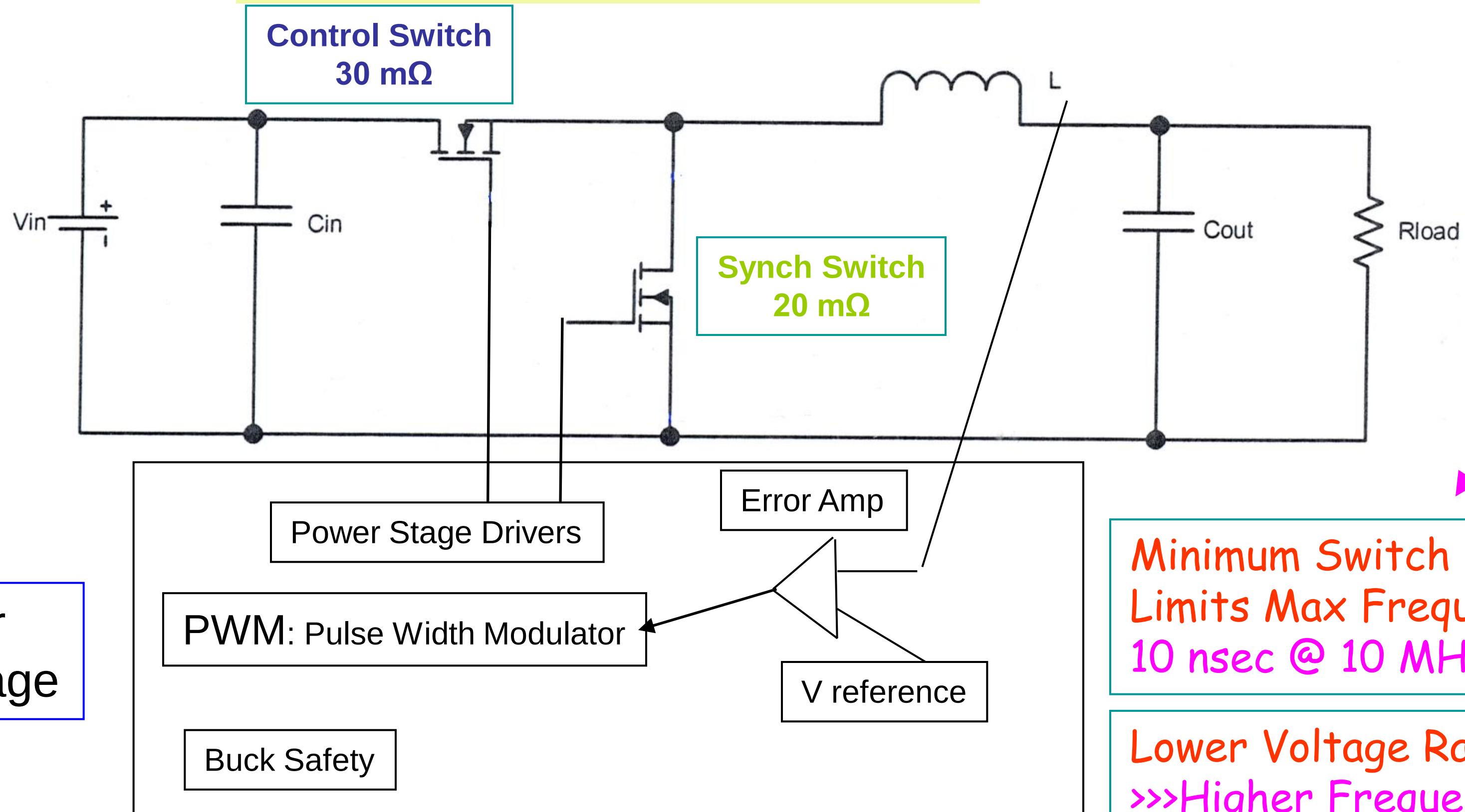
- Normally limited to integral fractions of input voltage
- Losses proportional to switch losses
- Can provide negative voltage

❖ Buck Converter – Used in consumer & Industrial Electronics

- Needs an ASIC, Inductor and Capacitors
- Cannot provide a negative voltage
- Topology allows for more flexibility in output voltage than charge pump
- Much more common use in commercial applications

Synchronous Buck Converter

Power Stage
-
High Volts

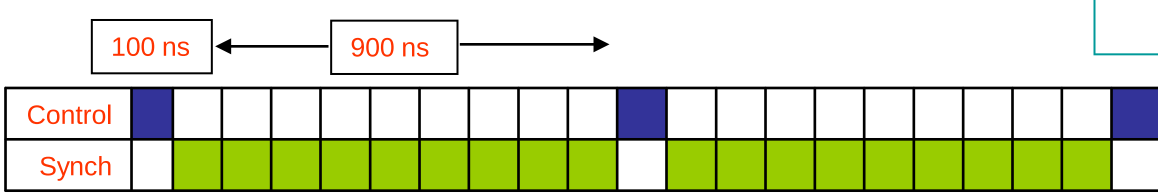


Controller
Low Voltage

Minimum Switch ON Time
Limits Max Frequency
10 nsec @ 10 MHz

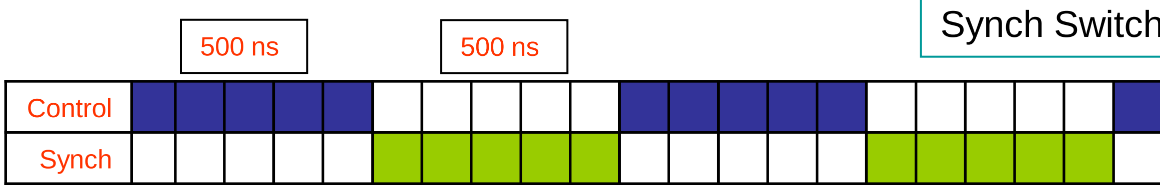
Lower Voltage Ratio
>>>Higher Frequency
& Smaller Coil

Vout = 11%

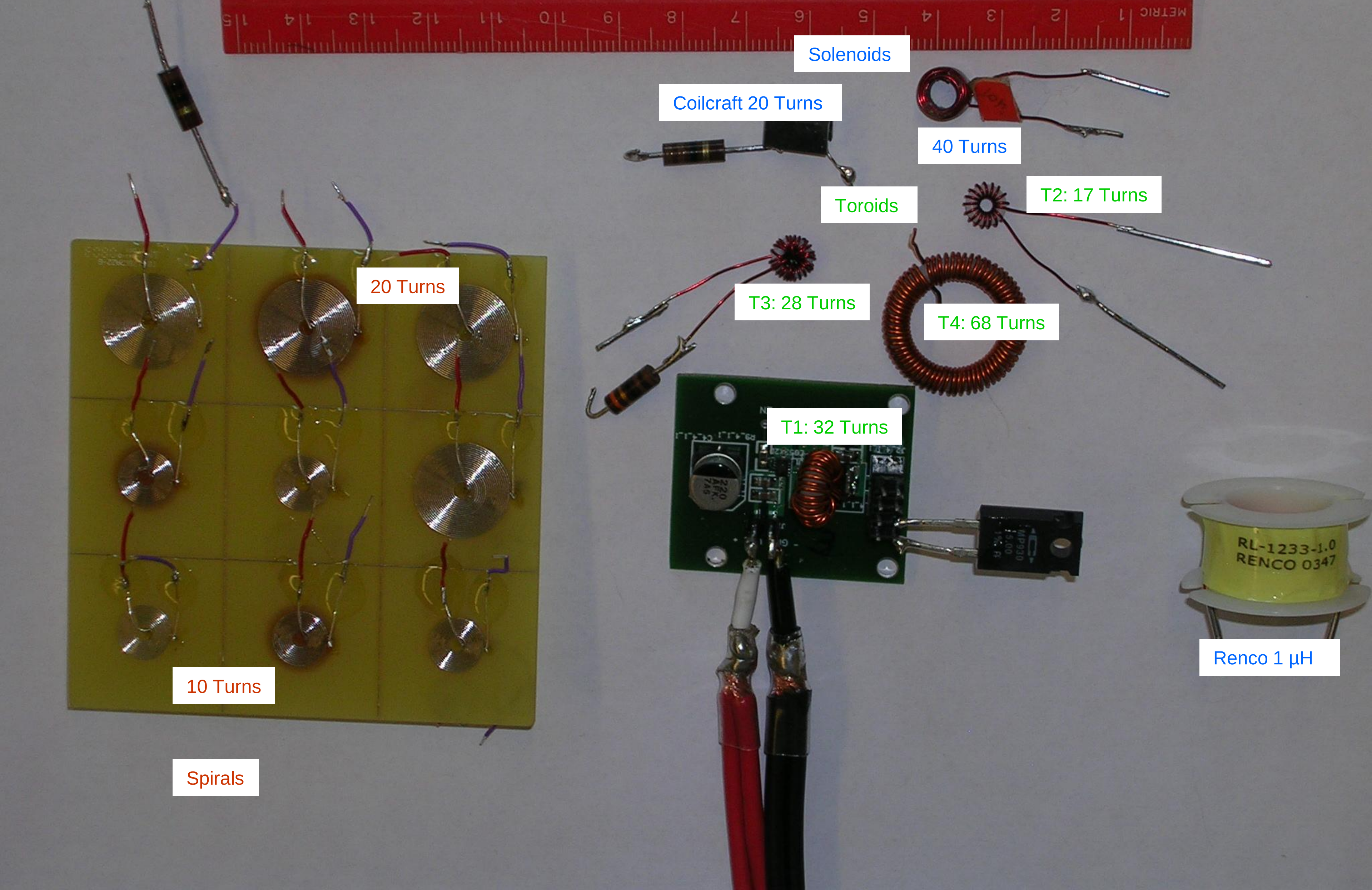


Control Switch: Switching Loss > I^2
Synch Switch: Rds Loss Significant

Vout = 50%



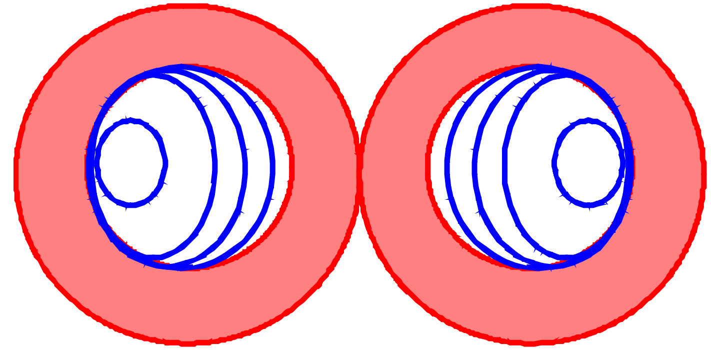
Coils under Study: Solenoid, Toroid, Spirals



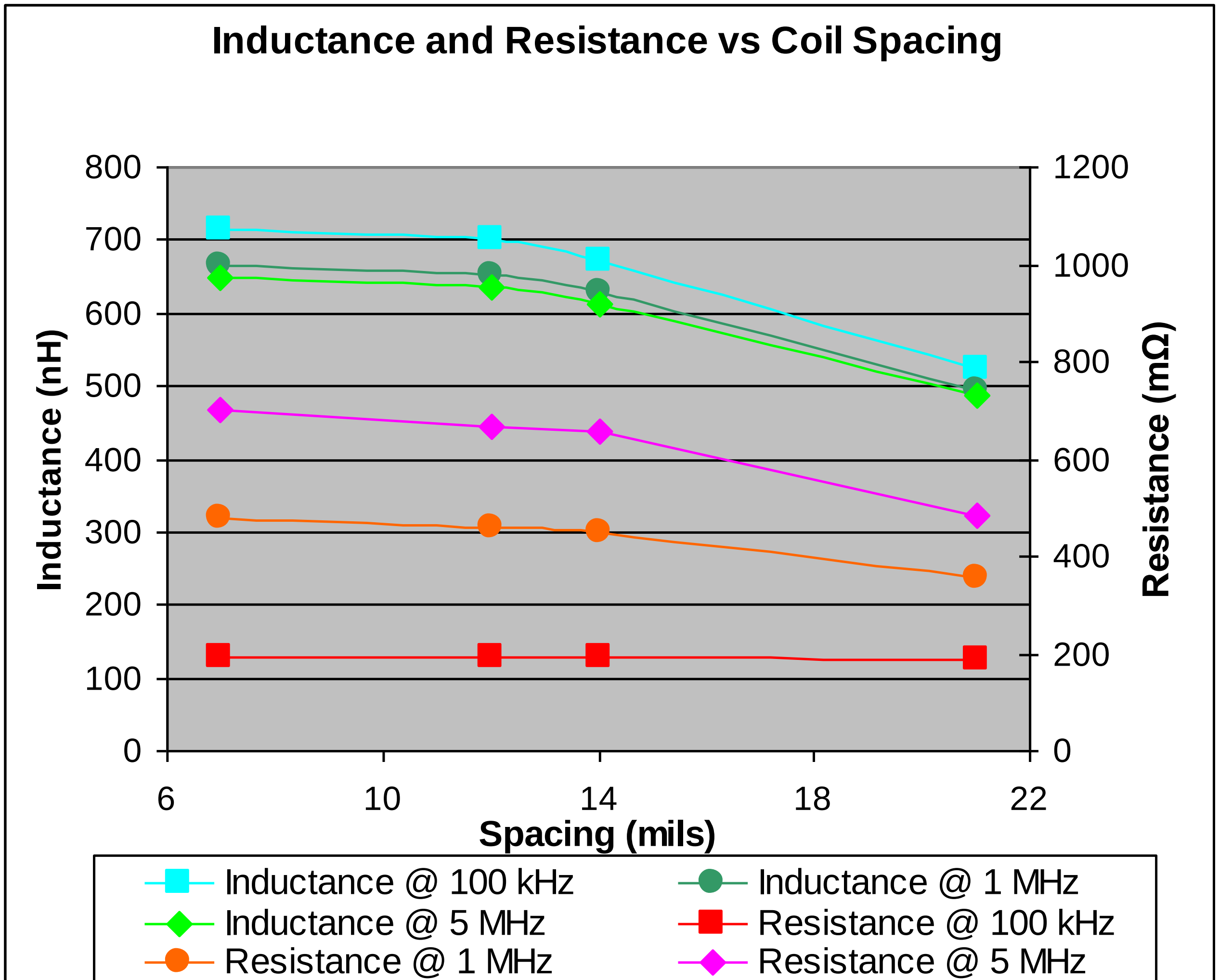
Proximity Effect

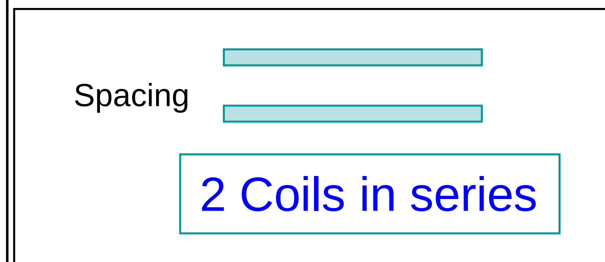
2 oz copper for coils

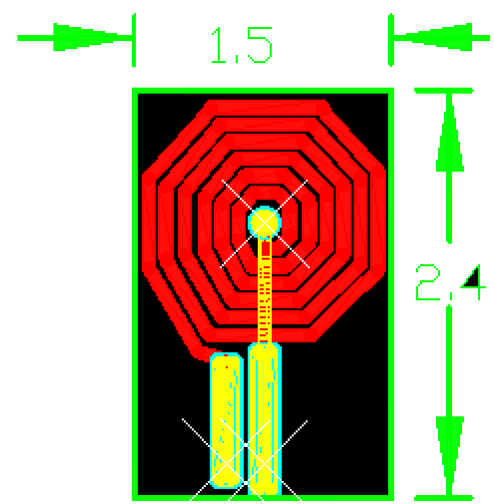
2 coils in series for larger L



Current Distribution in Neighboring Conductors

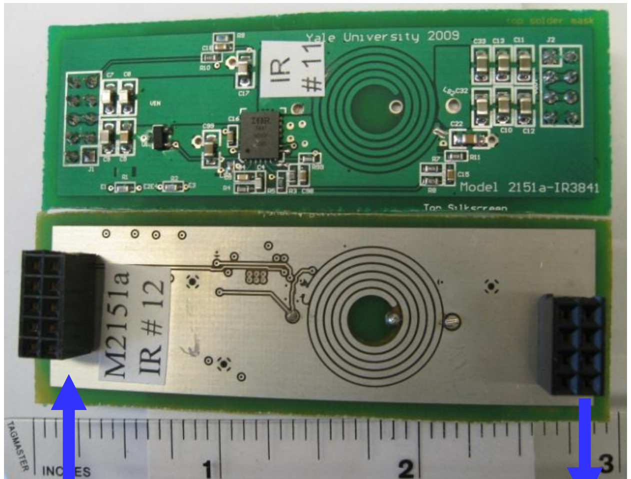






cms

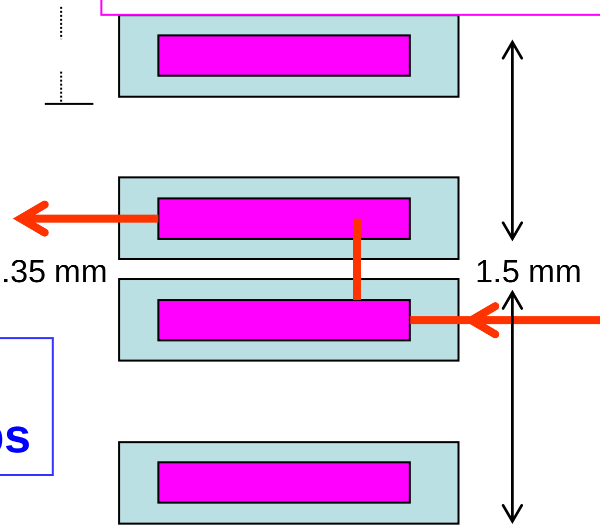
Plug In Card with Shielded Buck Inductor

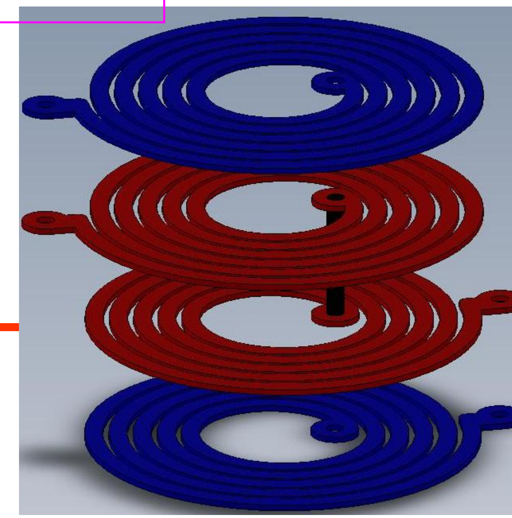


12 V

2.5 V
@ 6 amps

Coupled Air Core Inductor
Connected in Series



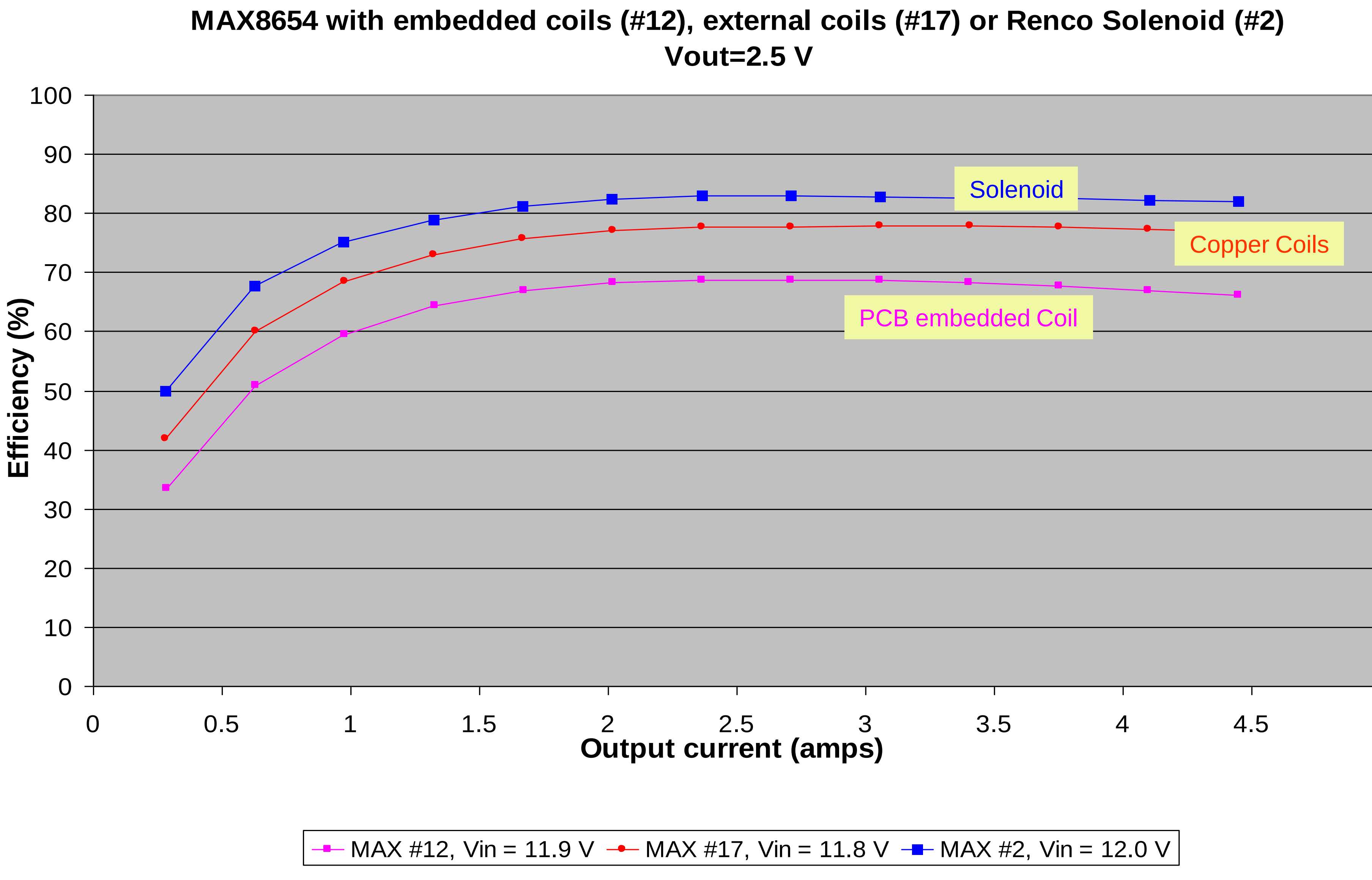


Different Versions

- Converter Chips
  - Max8654 monolithic
  - IR8341 3 die MCM
- Coils
  - Embedded 3oz cu
  - Solenoid 15 mΩ
  - Spiral Etched 0.25mm

Spiral Coils Resistance in mΩ

	Top	Bottom
3 Oz PCB	57	46
0.25 mm Cu Foil	19.4	17

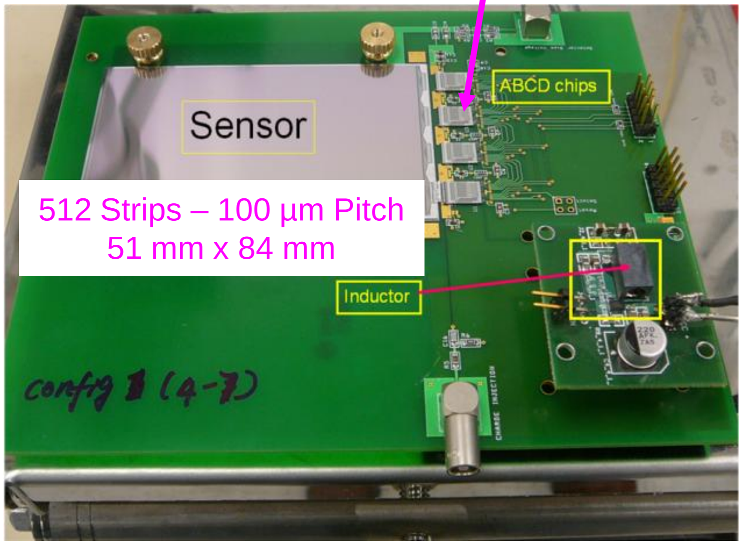


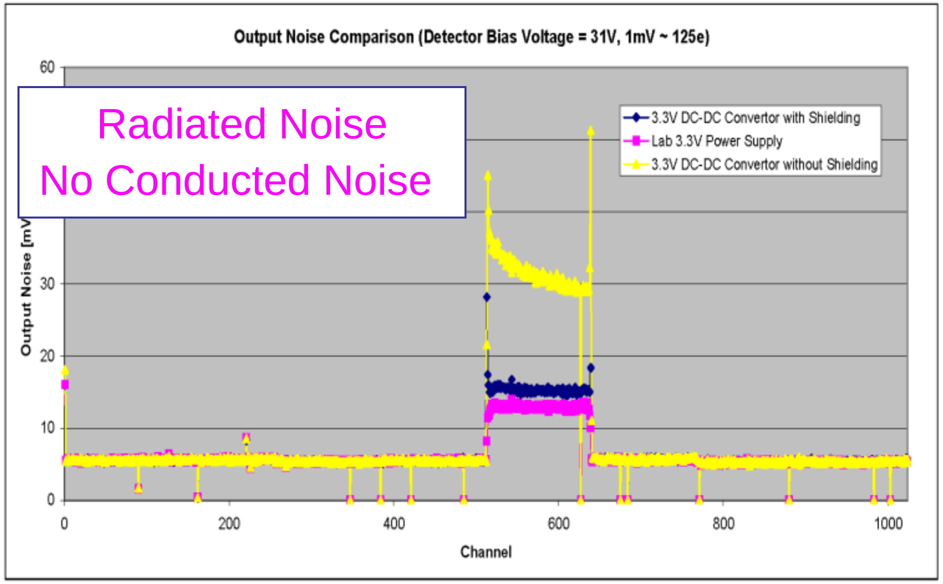
MAX8654 with embedded coils (#12), external coils (#17) or Renco Solenoid (#2)
Vout=2.5 V
Efficiency (%)
100
90
80
70
60
50
40
30
20
10
0
0
0.5
1
1.5
2
2.5
3
3.5
4
4.5
5
Output current (amps)
Solenoid
Copper Coils
PCB embedded Coil
MAX #12, Vin = 11.9 V
MAX #17, Vin = 11.8 V
MAX #2, Vin = 12.0 V

Noise Tests with Silicon Sensors

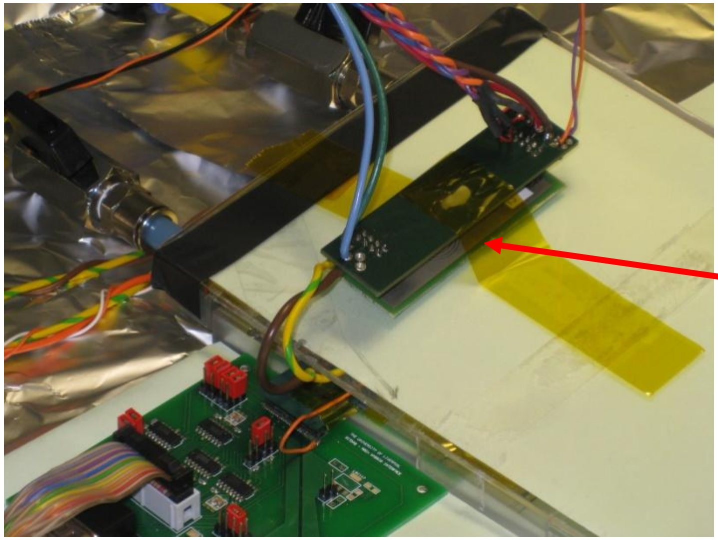
Test @ BNL

Only One Chip Bonded





Test @ Liverpool



Plug in Card
1 cm from Coil facing Sensor

20 µm Al foil shielding

Coil Type	Power	Input Noise electrons rms
Solenoid	DC - DC	881
Solenoid	Linear	885
Spiral Coil	DC - DC	666
Spiral Coil	Linear	664

DC-DC with Air Coil

Magnetic Field Effect

7 Tesla Field Chemistry Department Super Conducting Magnet in Persistence Mode

Effect:

Vout = 3.545 Outside

Vout = 3.546 Edge of magnet

Vout = 3.549 Center of magnet

Change= Increased Vout 1 part in 900 at 7T

Ionizing Radiation Results – Commercial Converters

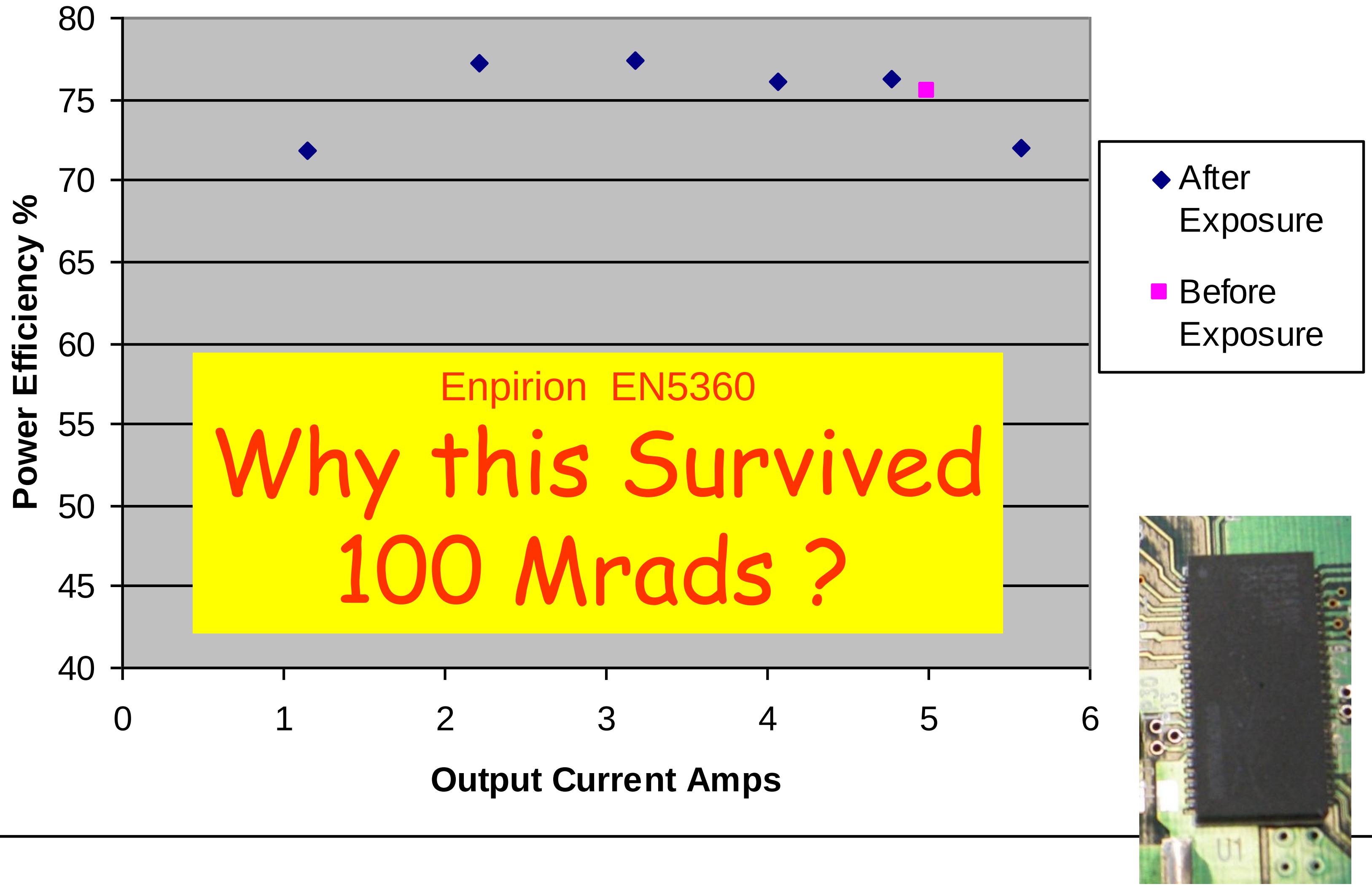
Dose rate= 0.2 Mrad/hr

Device	Time in Seconds	Dose before Damage Seen (krads)	Observations Damage Mode
TPS 62110	720	40	Increasing input current
ISL 8502	730	40.6	Increasing input current
MAX 8654	850	47.2	Loss of output voltage regulation
ADP 21xx	1000	55.6	Loss of output voltage regulation
ST1510	2250	125	Loss of output voltage regulation
IR3822	2500	139	Increasing input current
EN5382	2000	111	Loss of output voltage regulation
EN5360 #3	864000 Tested in 2008	48000	MINIMAL DAMAGE
EN5360 #2	Tested in 2007	100000	MINIMAL DAMAGE

5 nm Oxide DC-DC

Many more tested but similar failure-
Thin oxide converters survive > 200 Krads

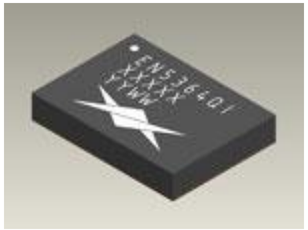
Buck Regulator Efficiency after 100 Mrad dosage

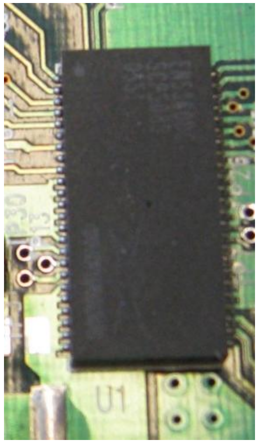


What Makes it Rad Resistant ?

Empirical Evidence: Deep submicron

But why?

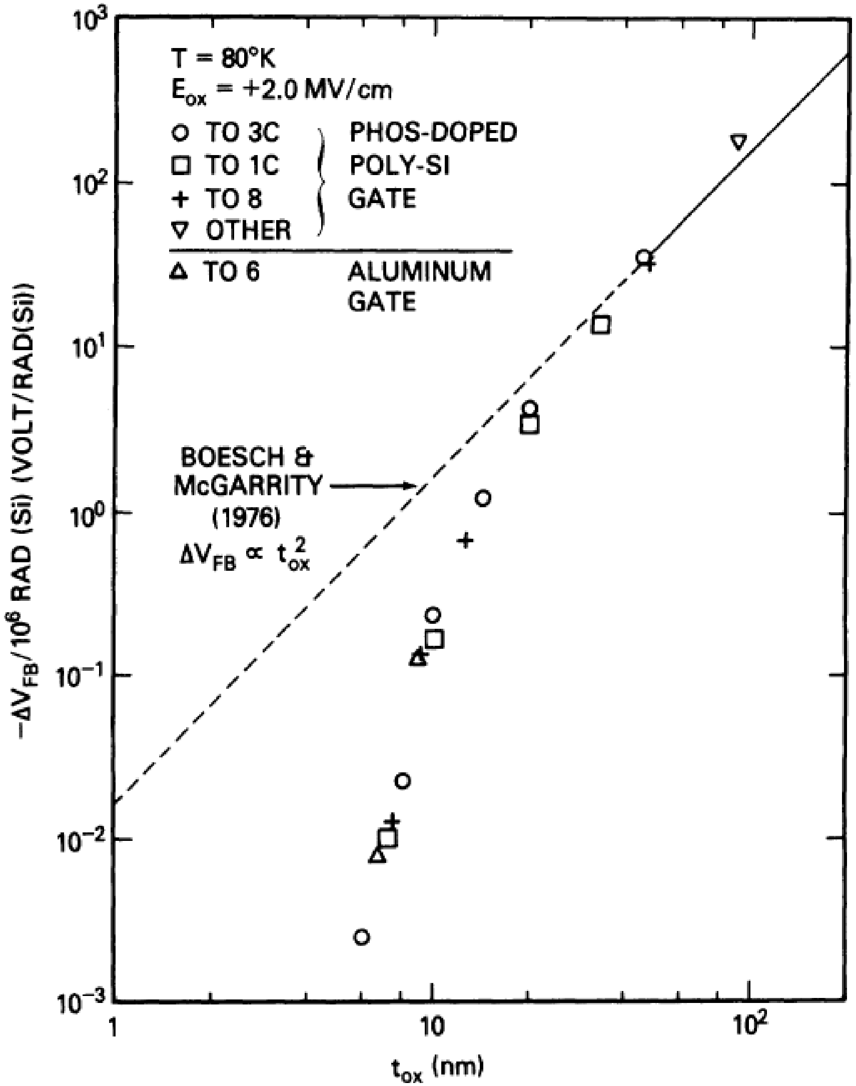




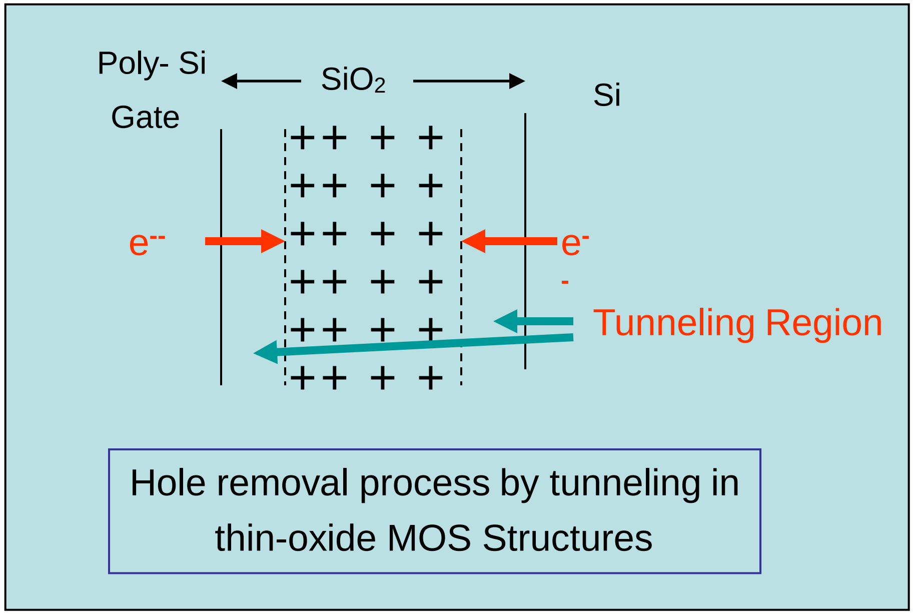
What Makes it Rad Resistant ?

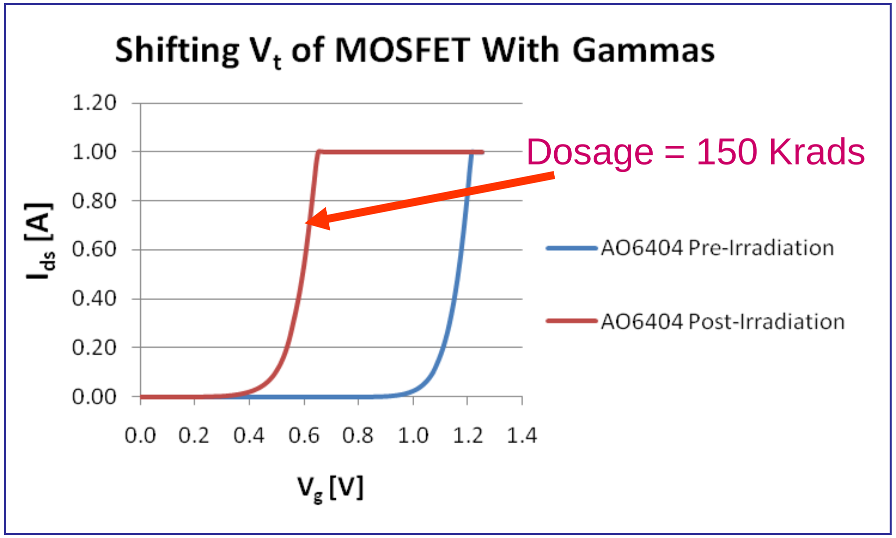
We say thin Gate Oxide is a necessary Condition

Threshold Shift vs Gate Oxide Thickness



Sachs et. al. IEEE Trans. Nuclear Science NS-31, 1249 (1984)





Book. Timothy R Oldham "Ionizing Radiation Effects in MOS Oxides" 1999 World Scientific

CERN ASICs

Mantra: Deep sub micron is more rad hard

Why ?

IBM Foundry Oxide Thickness			
Lithography	Process	Operating	Oxide
	Name	Voltage	Thickness
			nm
0.25 µm	6SF	2.5	5
		3.3	7
0.13 µm	8RF	1.2 & 1.5	2.2
		2.2 & 3.3	5.2

Can We Have
High Radiation Tolerance & Higher Voltage Together ???

Controller : Low Voltage

High Voltage: Switches –

LDMOS, Drain Extension, Deep Diffusion etc

>> 20 Volts HEMT GaN on Silicon, Silicon Carbide, Sapphire

LDMOS Structure

Laterally Diffused
Drain Extension

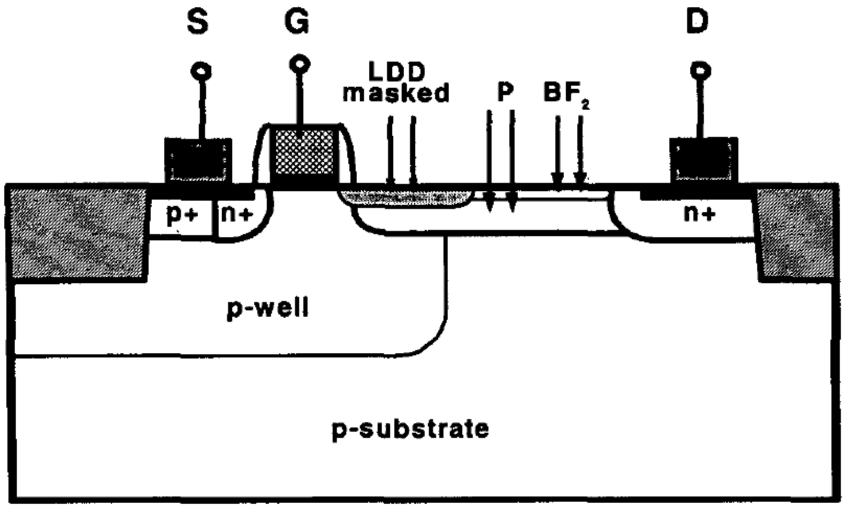


Fig.1: Schematic cross-section of the RF-LDMOS transistor.

High Voltage / high Frequency
Main market. Cellular base stations

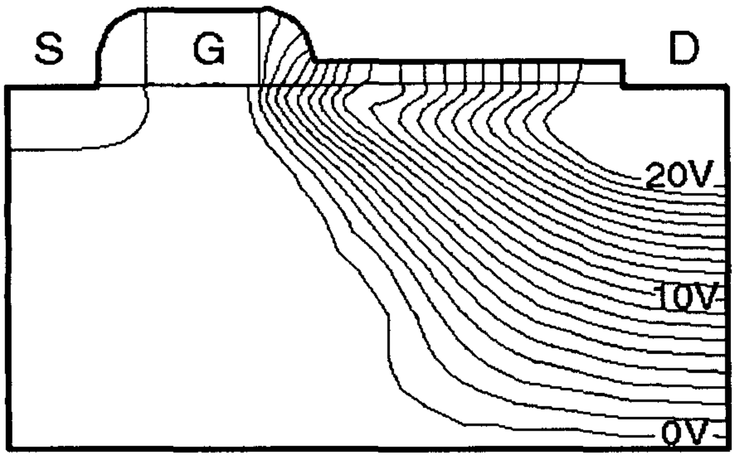


Fig.3a: Potential distribution at the highest operating voltage (20V) with $V_G = 0V$ (LDMOS 3 from Table 1).

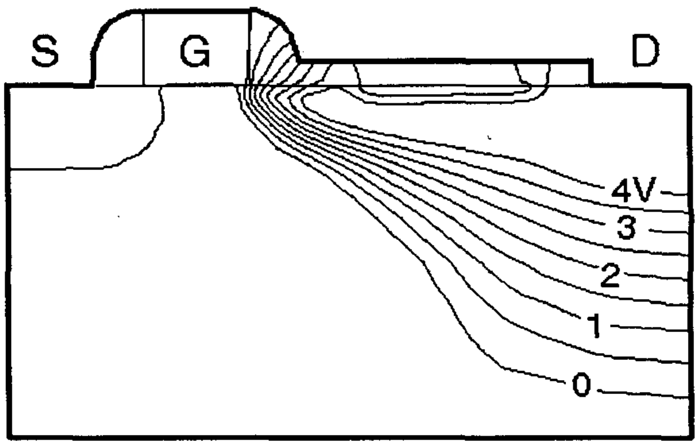


Fig.3b: Potential distribution at the lowest operating voltage (4V) with $V_G = 0V$ (LDMOS 3 from Table 1).

High performance RF LDMOS transistors with 5 nm gate oxide in a 0.25 µm SiGe:C BiCMOS technology: IHP Microelectronics
Electron Devices Meeting, 2001. IEDM Technical Digest. International
2-5 Dec. 2001 Page(s):40.4.1 - 40.4.4

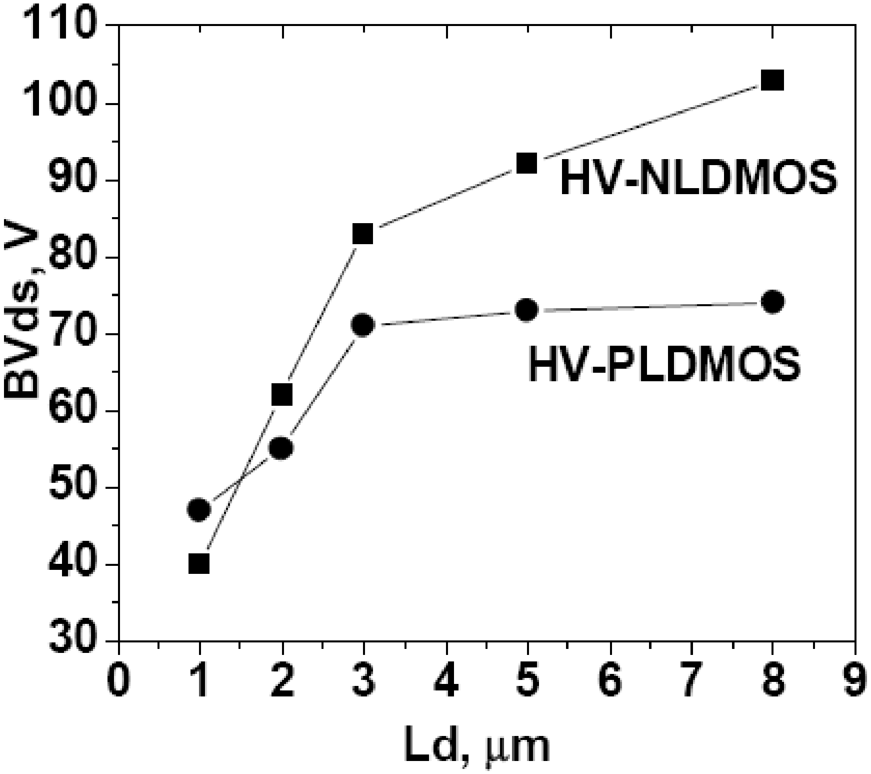


Fig. 6. BVdss as function of drift length Ld. Saturation of BVdss for PLDMOS due to onset of vertical break down.

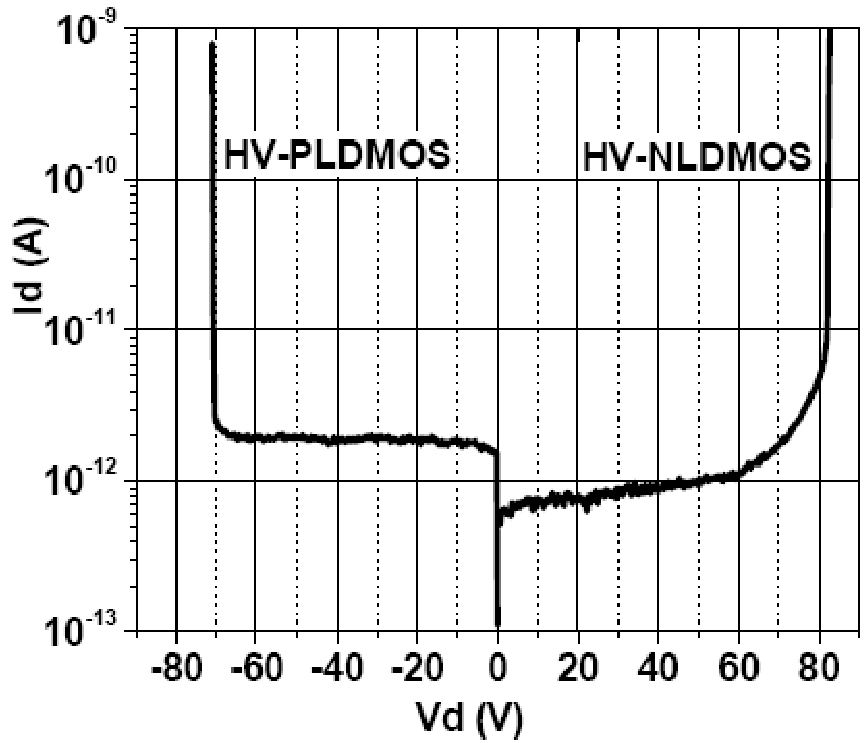


Fig. 7. Break down characteristics of PLDMOS and NLDMOS (w = 5.6 µm, Ld = 3 µm).

R. Sorge et al , IHP Proceedings of SIRF 2008 Conference

High Voltage Complementary Epi Free LDMOS Module with 70 V PLDMOS for a 0.25 µm SiGe:C BiCMOS Platform

Thin Oxide Devices (non IBM)

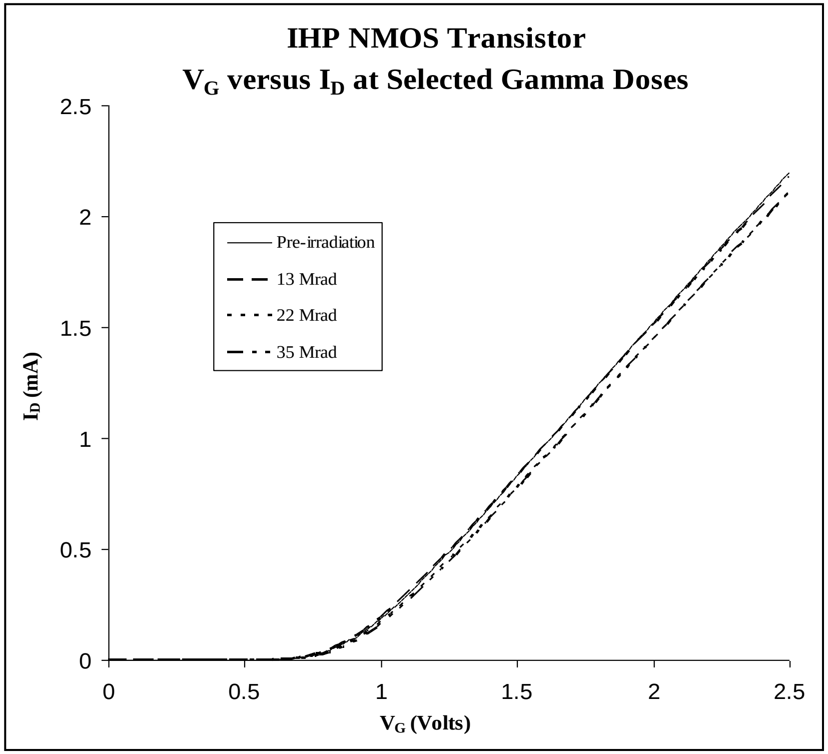
Company	Device	Process	Foundry	Oxide	Dose before	Observation
		Name/ Number	Name	nm	Damage seen	Damage Mode
IHP	ASIC custom	SG25V GOD **12 V**	IHP, Germany	5		Minimal Damage
XySemi	FET 2 amps	HVMOS20080720 **12 V**	China	7		Minimal Damage
XySemi	XP2201	HVMOS20080720 **15 V**	China	12 / 7		1Q2010
Enpirion	EN5365	CMOS 0.25 µm	Dongbu HiTek, Korea	5	64 Krads	
Enpirion	EN5382	CMOS 0.25 µm	Dongbu HiTek, Korea	5	111 Krads	
Enpirion	EN5360 #2	SG25V (IHP)	IHP, Germany	5	100 Mrads	Minimal Damage
Enpirion	EN5360 #3	SG25V (IHP)	IHP, Germany	5	48 Mrads	Minimal Damage

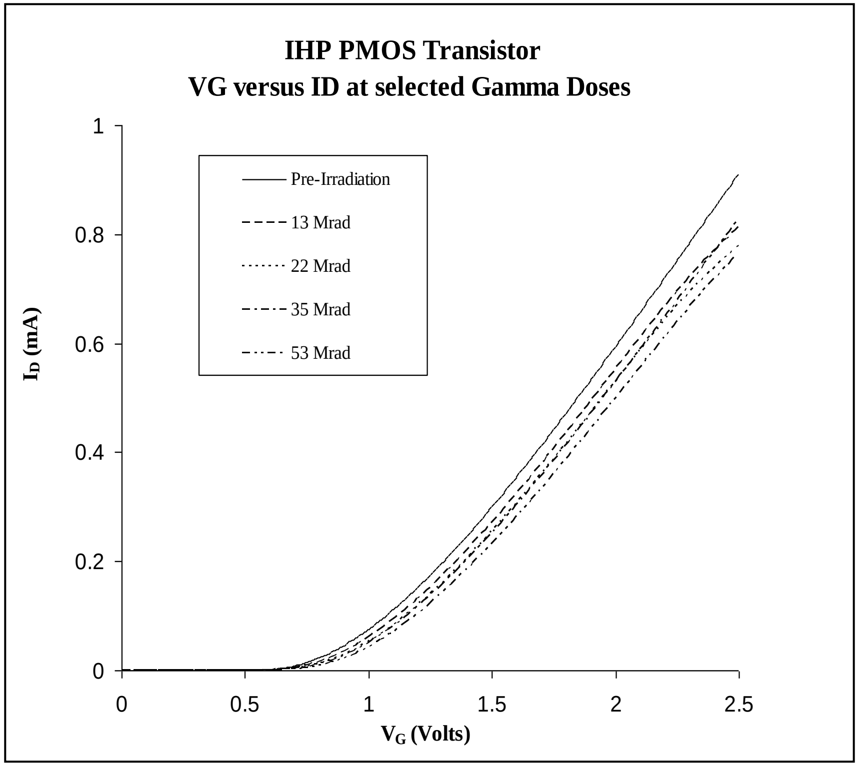
Necessary condition for Radiation Hardness - Thin Gate Oxide

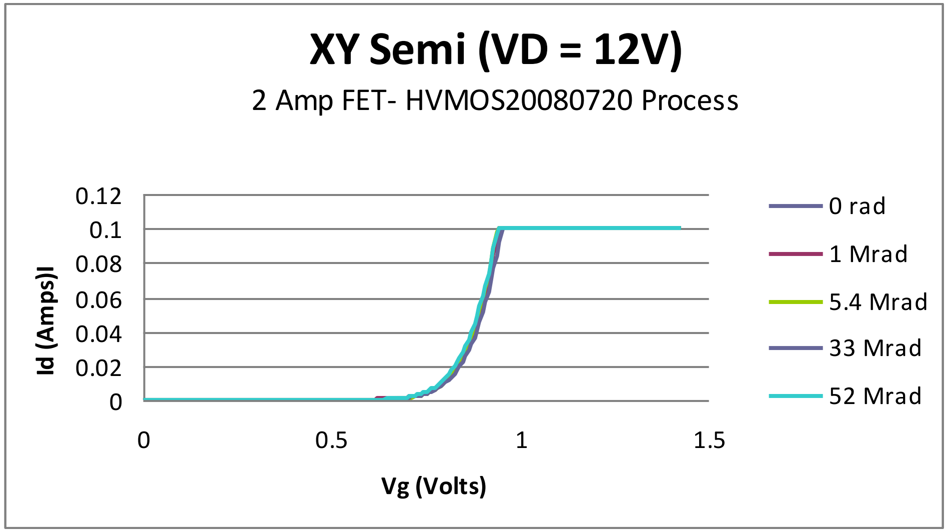
But not sufficient

IHP: Epi free, High resistivity substrate, Higher voltage, lower noise devices

Dongbu: Epi process on substrate, lower voltage due to hot carriers in gate oxide


IHP NMOS Transistor
V_G versus I_D at Selected Gamma Doses
2.5
2
1.5
1
0.5
0
0
0.5
1
1.5
2
2.5
I_D (mA)
V_G (Volts)
Pre-irradiation
13 Mrad
22 Mrad
35 Mrad

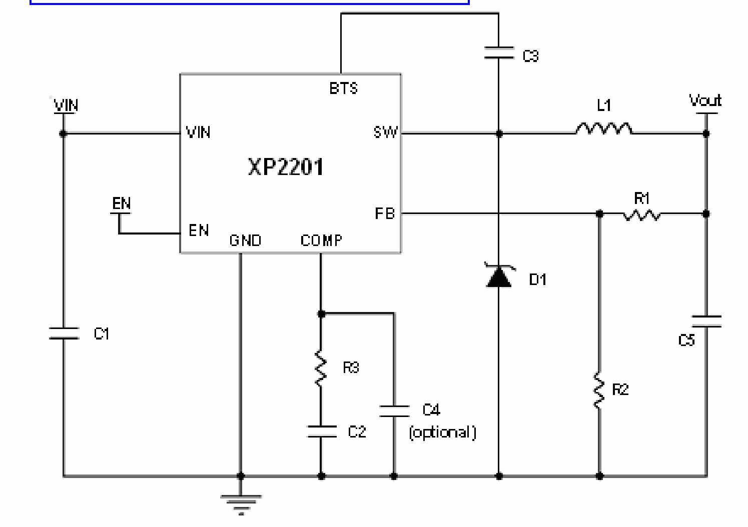

IHP PMOS Transistor
VG versus ID at selected Gamma Doses
1
0.8
0.6
0.4
0.2
0
0
0.5
1
1.5
2
2.5
I_D (mA)
V_G (Volts)
Pre-Irradiation
13 Mrad
22 Mrad
35 Mrad
53 Mrad


XY Semi (VD = 12V)
2 Amp FET- HVMOS20080720 Process
0.12
0.1
0.08
0.06
0.04
0.02
0
0
0.5
1
1.5
Id (Amps)l
Vg (Volts)
0 rad
1 Mrad
5.4 Mrad
33 Mrad
52 Mrad

XP2201 - 20V 2A STEP-DOWN DC to DC CONVERTER

General Description

Non- Synchronous

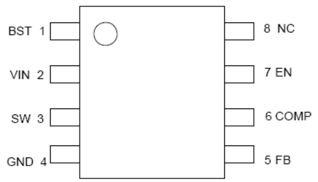


Replacement for LHC4913:
LHC Radiation Hard LDO
Made by ST Microelectronics

Use with Ferrite Coil

Features

- 2A Output Current
- Up to 95% Efficiency
- 4.5V to 20V Input Range
- Adjustable Output Voltage
- Fixed 400KHz Frequency
- Integrated 0.2Ω Switch
- 20uA Shutdown Supply Current
- Internal Soft Start
- Cycle-by-Cycle Over Current Protection
- Thermal Shutdown
- Programmable Under Voltage Lockout
- Operating Temperature: -40°C to +85°C
- Available in an 8-Pin SO Package



SOP-8

Engineering Samples
1Q2010

GaN HEMTs Why of Interest?

- High voltage and current rating
- Very high switching frequency (> 1 GHz range)
- Depletion mode are radiation Hard (details follow), Enhancement mode devices not yet available. One brand in March 2010

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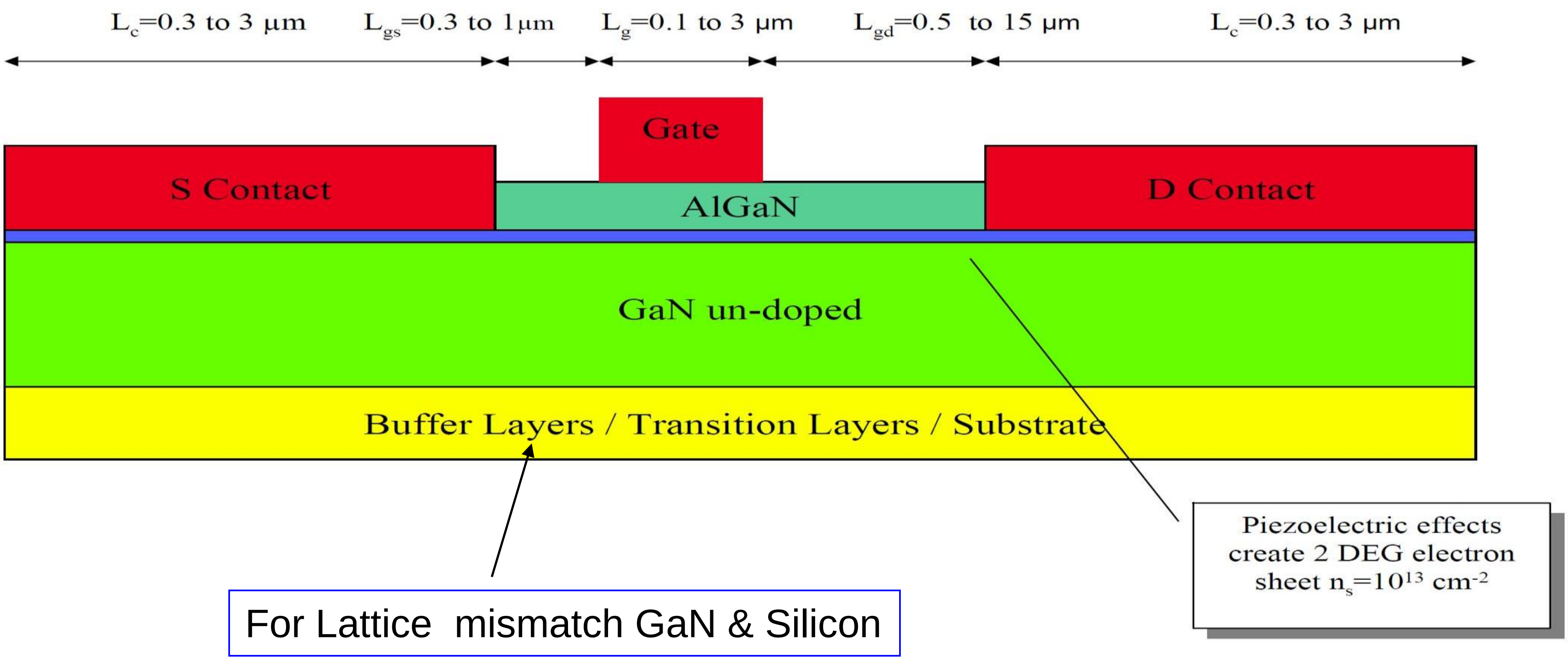
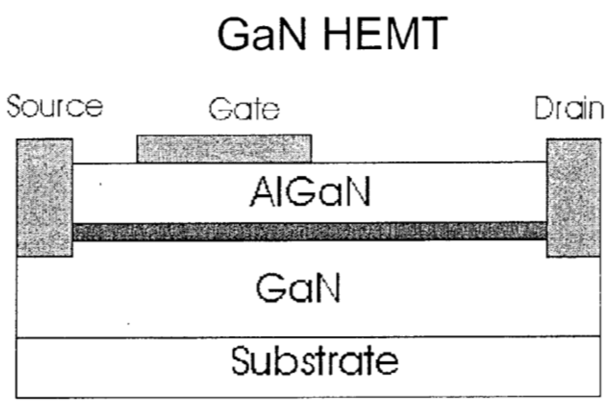
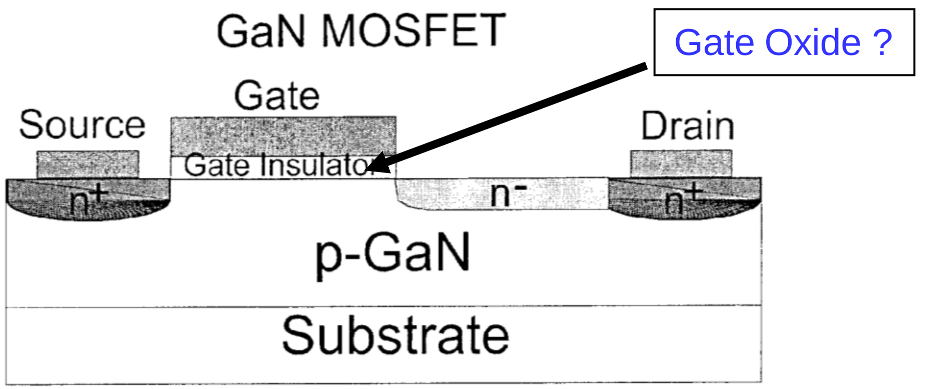
GaN for Power Switching



No Gate Oxide
High Dielectric strength
High Thermal conductivity





- Low on-resistance due to high Channel mobility (1500 $cm^2/V\text{-}s$) and sheet electron density ($1\times10^{13} cm^{-2}$)
- High gate leakage current (reduced by hybrid MOS-HEMT structure)
- Small conduction band offset between AlGaN and GaN

Depletion Mode
Normally ON

- Inversion-mode, normally-off operation
- Blocking voltage controlled by dopants incorporated by epi-growth or ion-implantation
- Low gate leakage current

Enhancement Mode
Normally OFF

Gallium Nitride Devices under Tests

RF GaN 20 Volts & 0.1 amp

- ❖ 8 pieces: Nitronex NPT 25015: GaN on Silicon
  - ✓ Done Gamma, Proton & Neutrons
  - ✓ 65 volts Oct 2009
- ❖ 2 pieces: CREE CGH40010F: GaN on siC
- ❖ 6 pieces: Eudyna EGNB010MK: GaN on siC
  - ✓ Done Neutrons

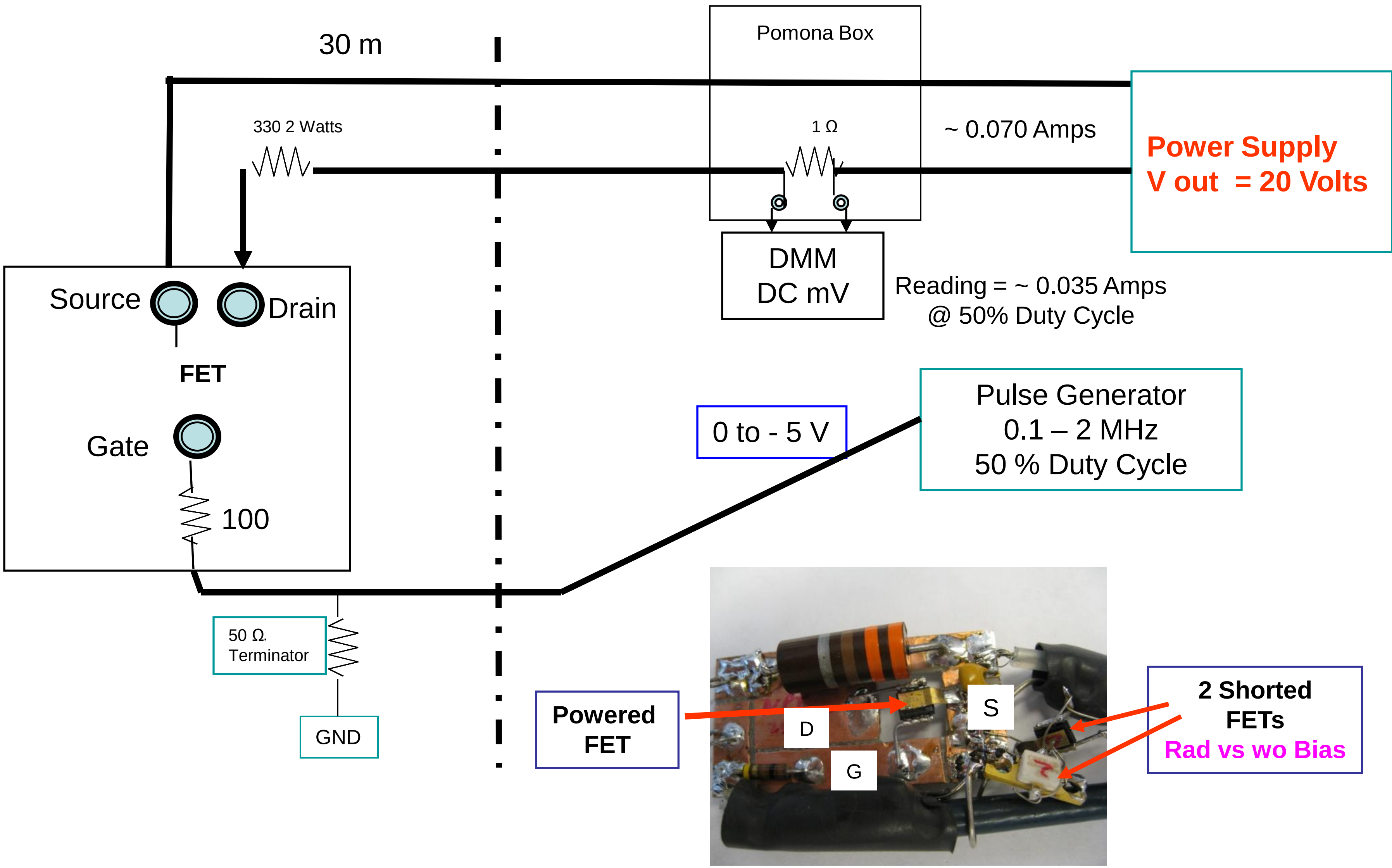
Switch GaN

- ❖ International Rectifier GaN on Silicon
  Under NDA

Gamma: @ BNL
Protons: @ Lansce
Neutrons: @ U of Mass Lowell

Plan to Expose same device to Gamma, Protons & Neutrons Online Monitoring

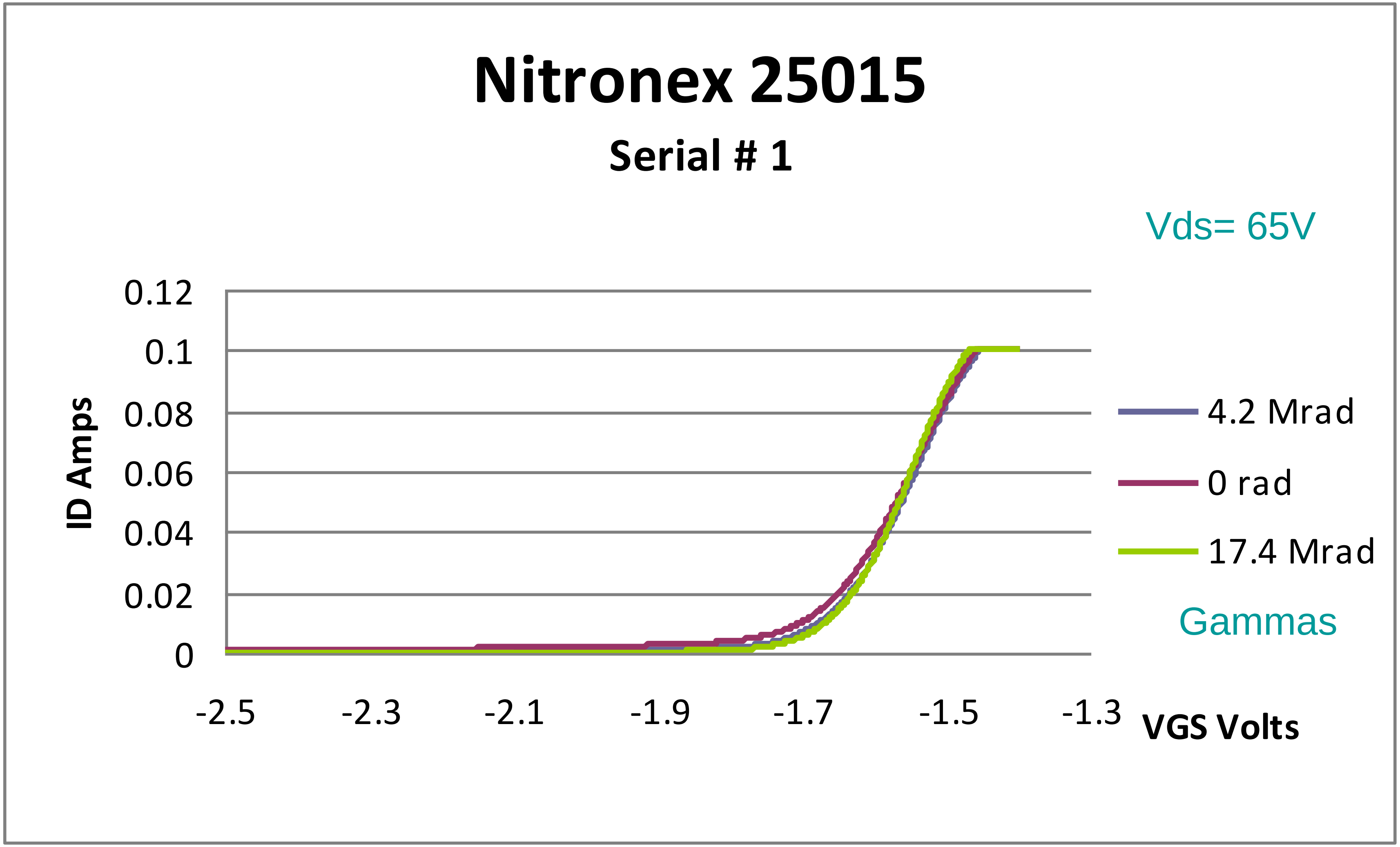
Bias during Radiation
Max operating V & I Limit Power by duty cycle



FET Setup for Proton Radiation Exposure

Satish Dhawan, Yale University

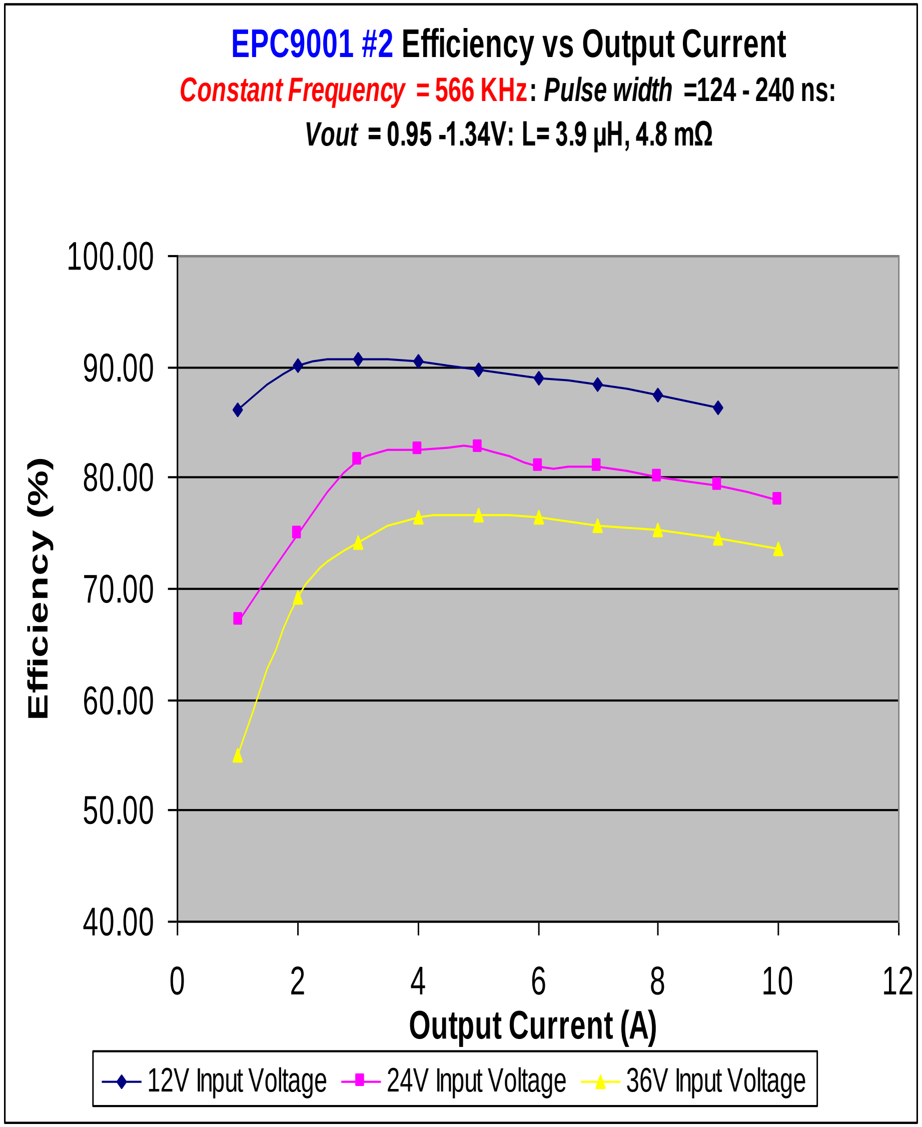
July 28. 2009

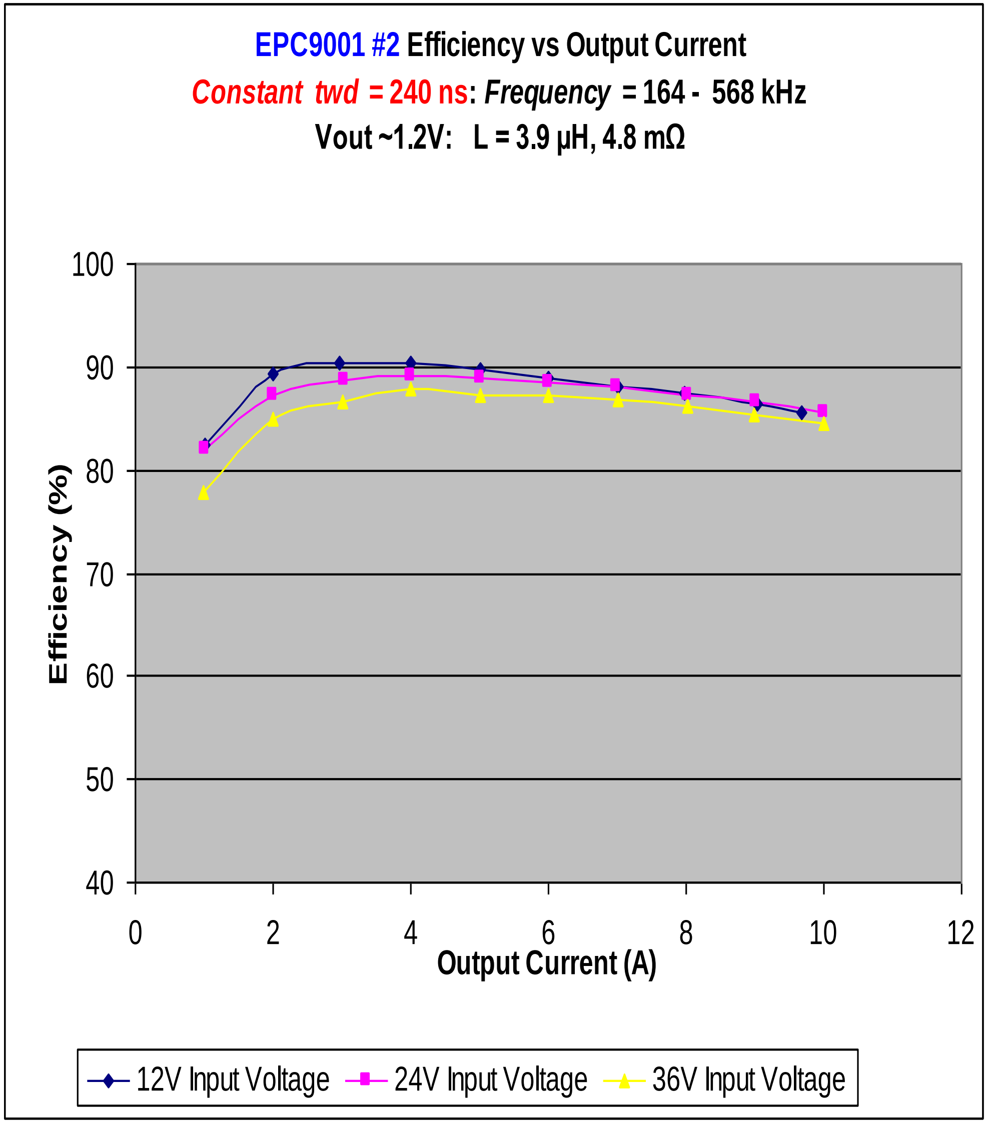


200 Mrads of Protons had no effect – switching 20 V 0.1 Amp
Parts still activated after 7 months

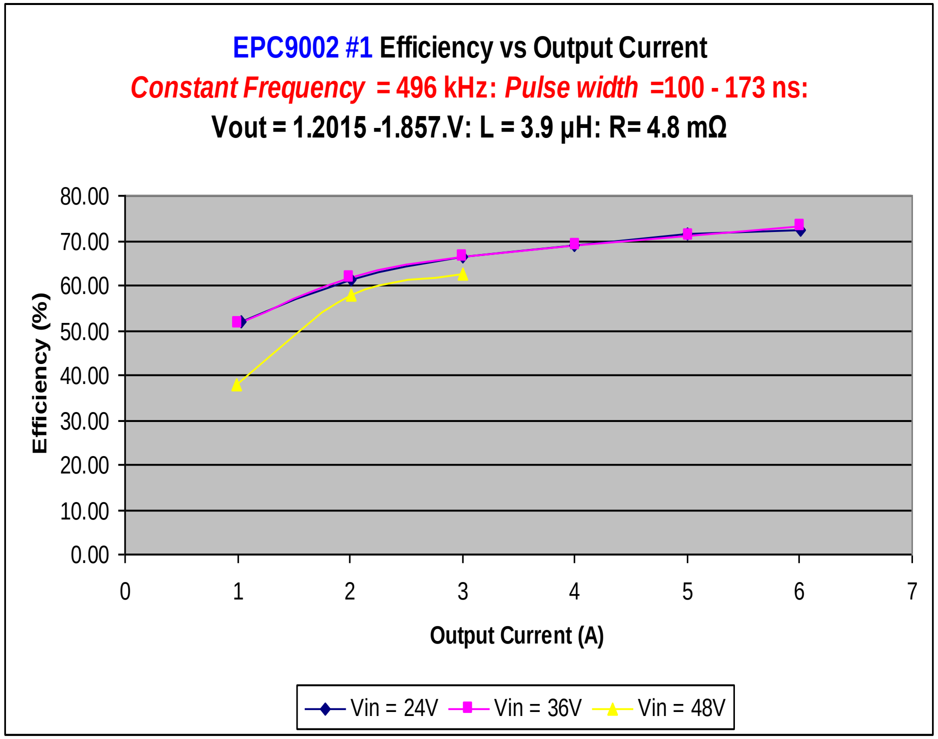
New GaN Devices for Power Switching

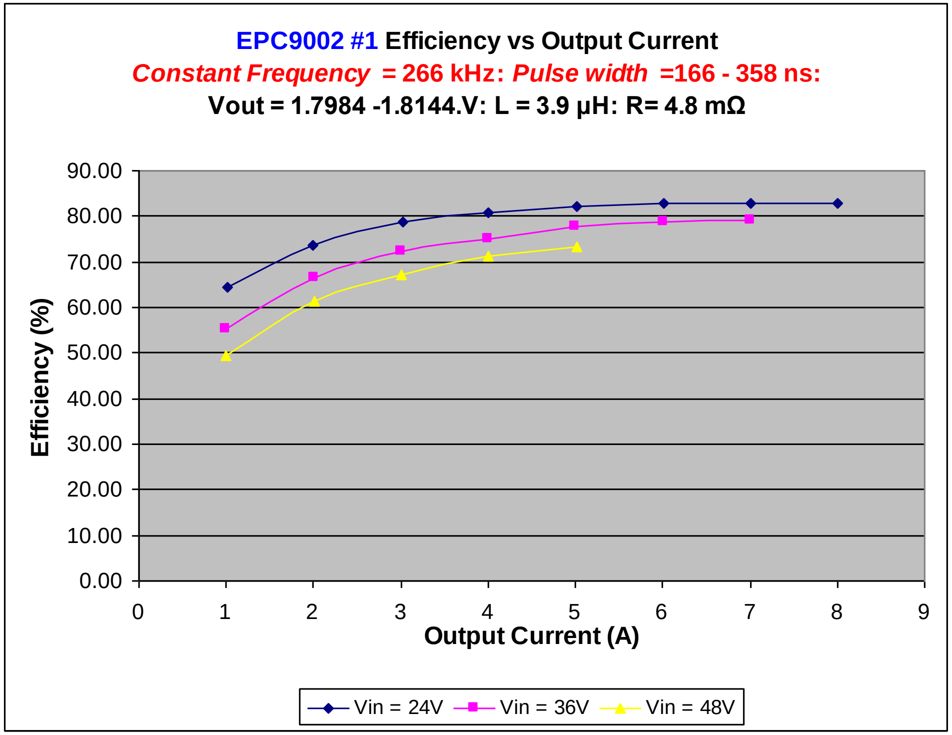
: Converter Efficiency Inputs = 12, 24 & 36 volts
output ~ 1.2 v



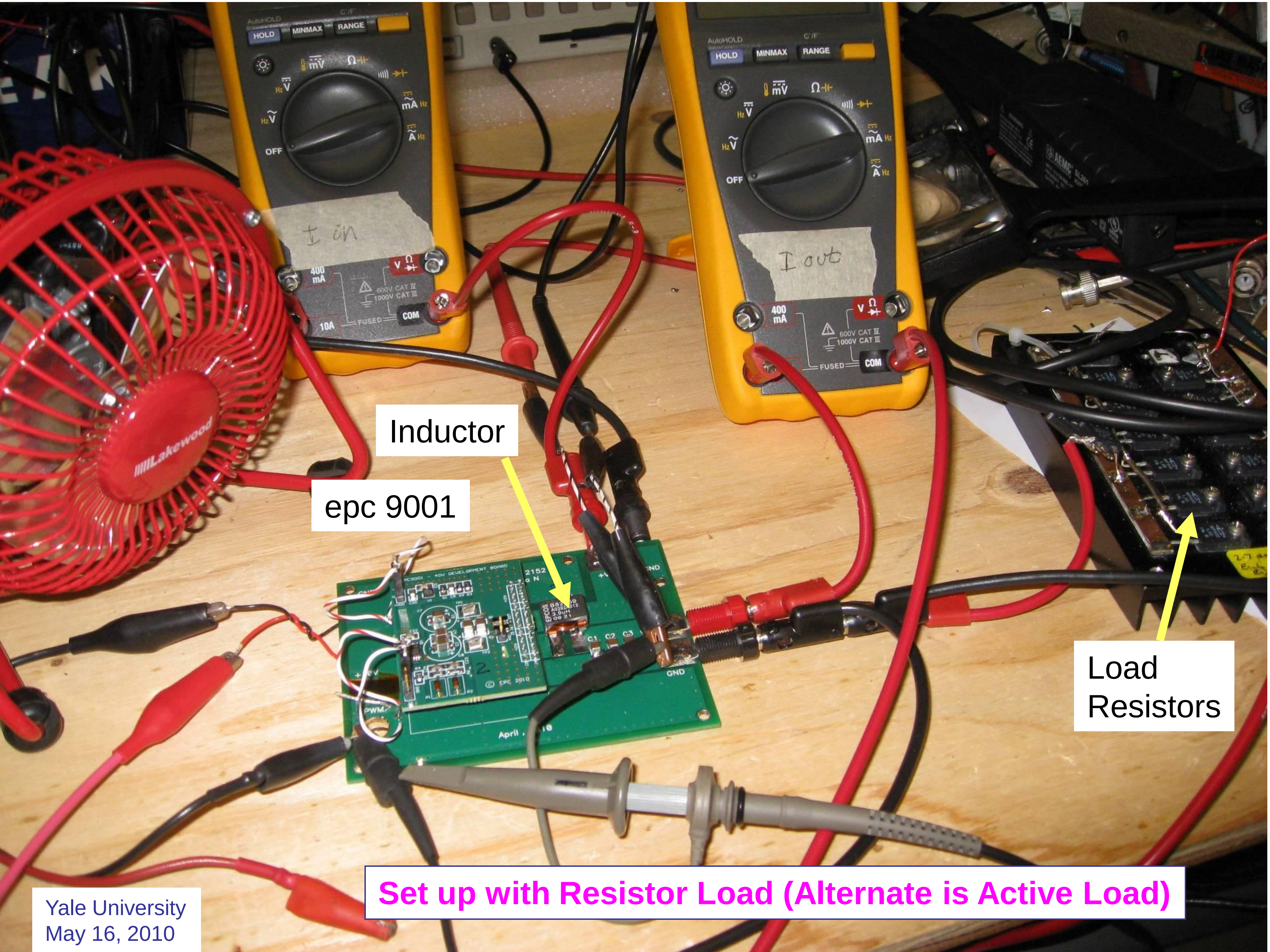


Converter Efficiency Inputs = 24 & 36 volts output ~ 1.8 v





Longer On Time improves efficiency (Lower Frequency)



Set up with Resistor Load (Alternate is Active Load)

6 times Higher Frequency over Si Solution with similar efficiency !

Silicon based POL :
15 mm x 15 mm

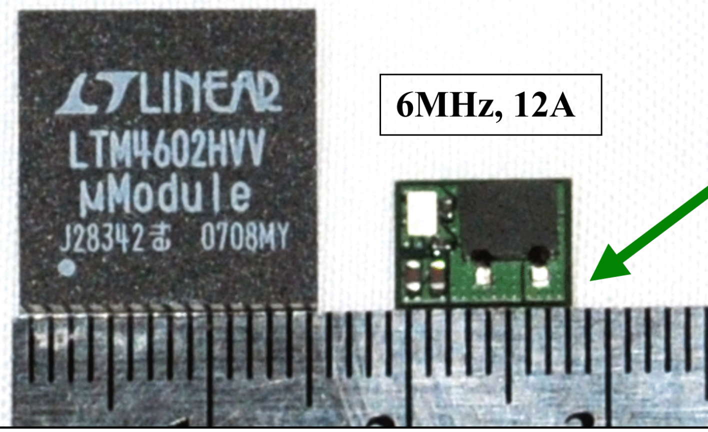
IR GaNpowIR

Gen 1.1 Solution:
6 mm x 9 mm….

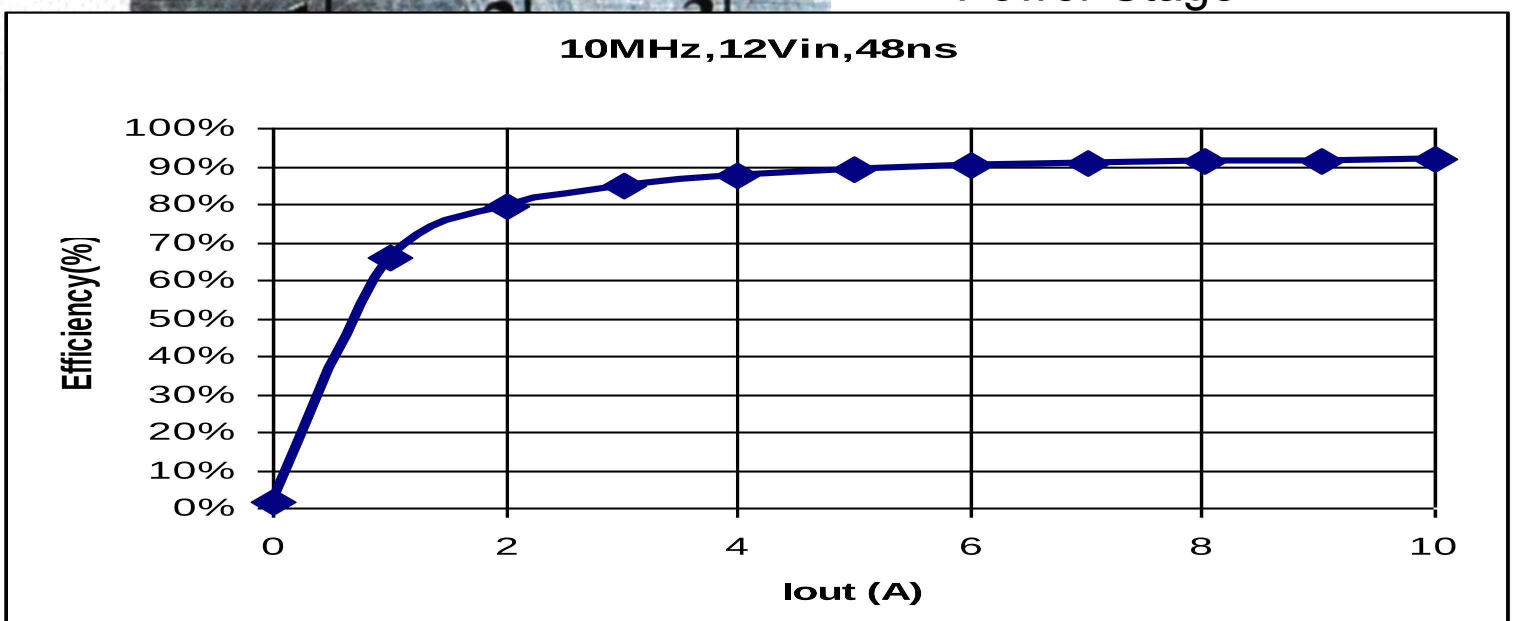
75 +% Smaller!

1MHz, 10A

6MHz, 12A

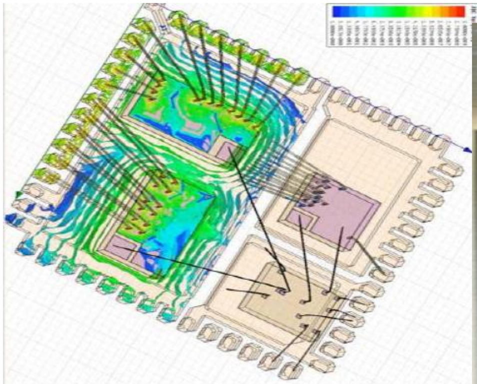


We had a later version
of the Engineering sample

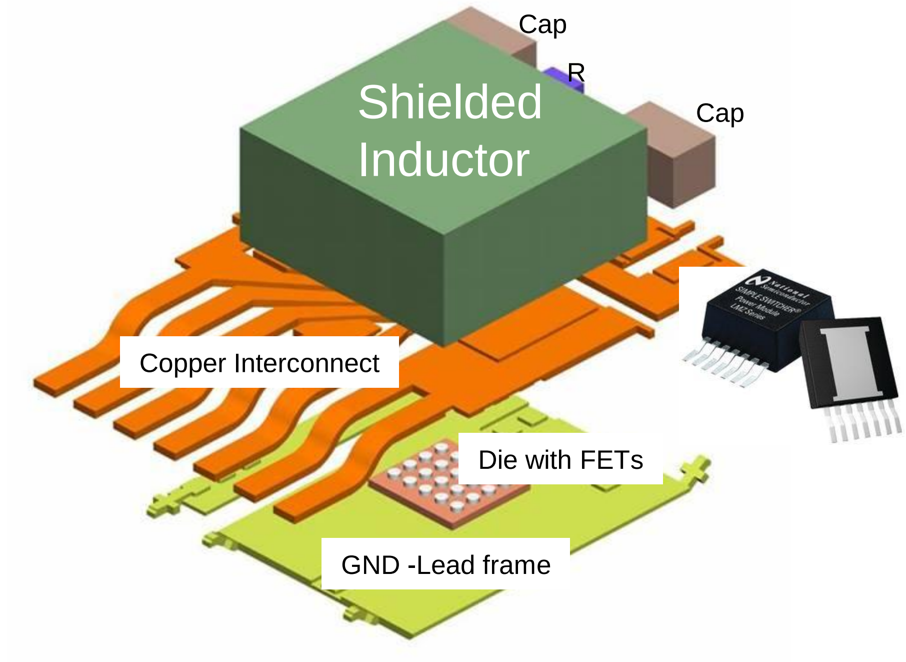


PSOC: Power Supply On a Chip

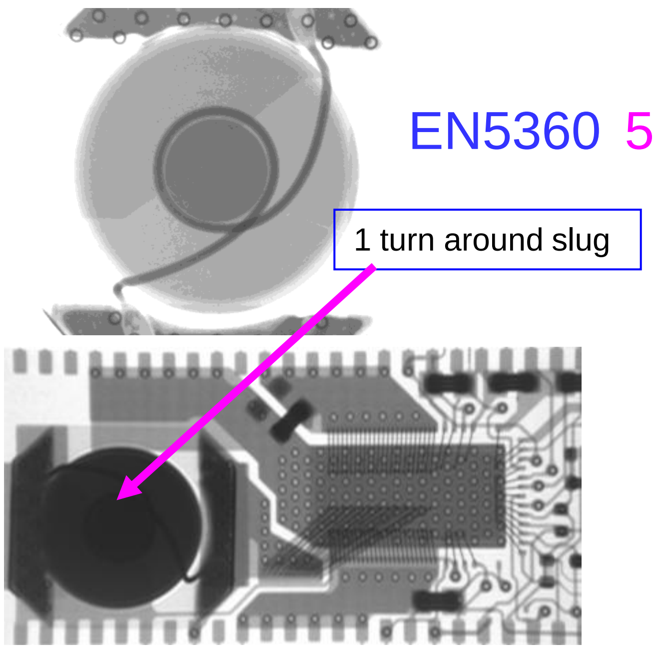
National: LMZ Package 10 x14 x5 mm 20/42 V > 1.2V 5 A

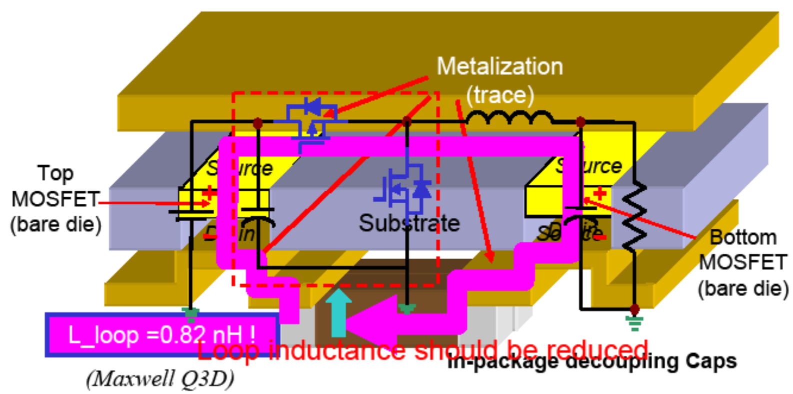


FAN5009 8 x 8 mm MCM
12 V > 1.2 V = 88.5% @ 30 A



EN5360 5 MHz





❖ Embedding the flipped devices allows for smallest loop inductance and for layering of components on top and bottom

PSOC: Power Supply On Chip

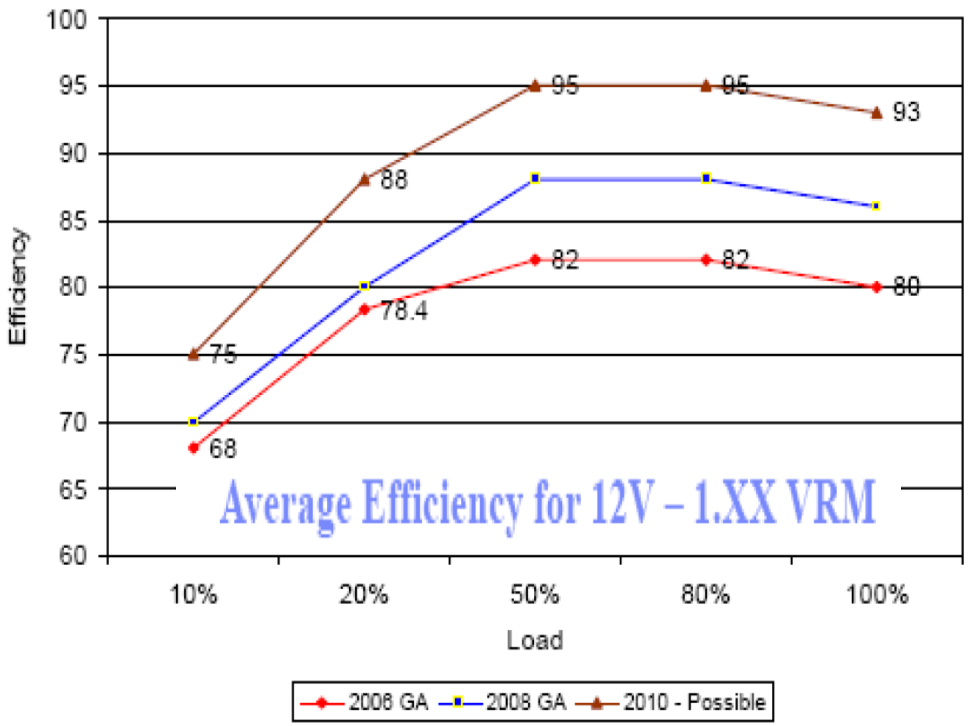
PSMA: Road Maps
Power Supply Manufacturer Association
Yale University is member

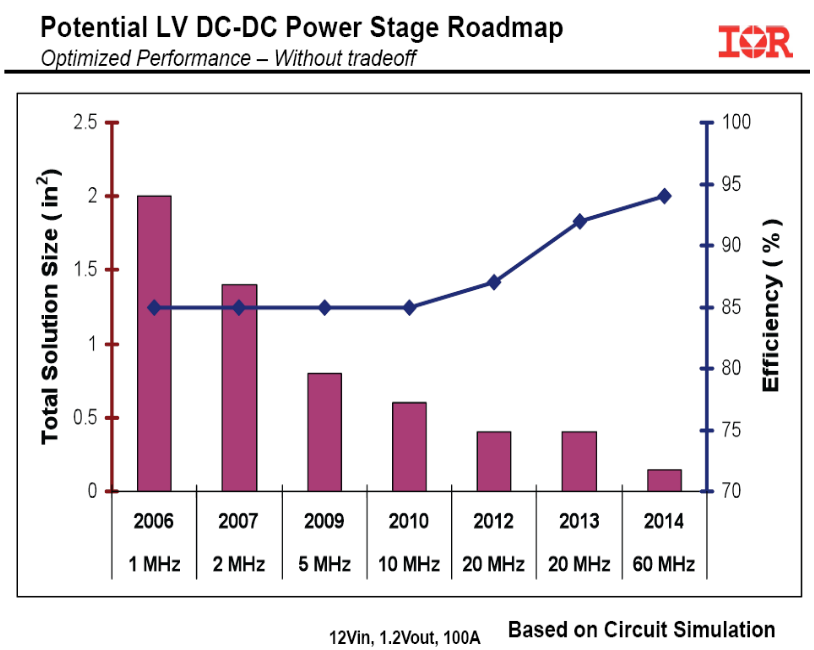
What is happening outside HEP ?

Server Power System Distribution from IBM

1. **AC Distribution - 208/230/115V**
   - o Servers, Blade Servers, Workstations
2. **12V DC Distribution**
   - o Blade Server Chassis, Low end and Midrange Servers, Workstations
3. **48V Distribution in a Rack**
   - o High End Server Applications
4. **350V DC Distribution in a Server Rack or a Rectifier Cabinet**
   - o Main Frame Servers

International Workshop on Power Supply On Chip
Sept 22nd - 24, 2008
Cork, Ireland





Is there a Commercial product available ?

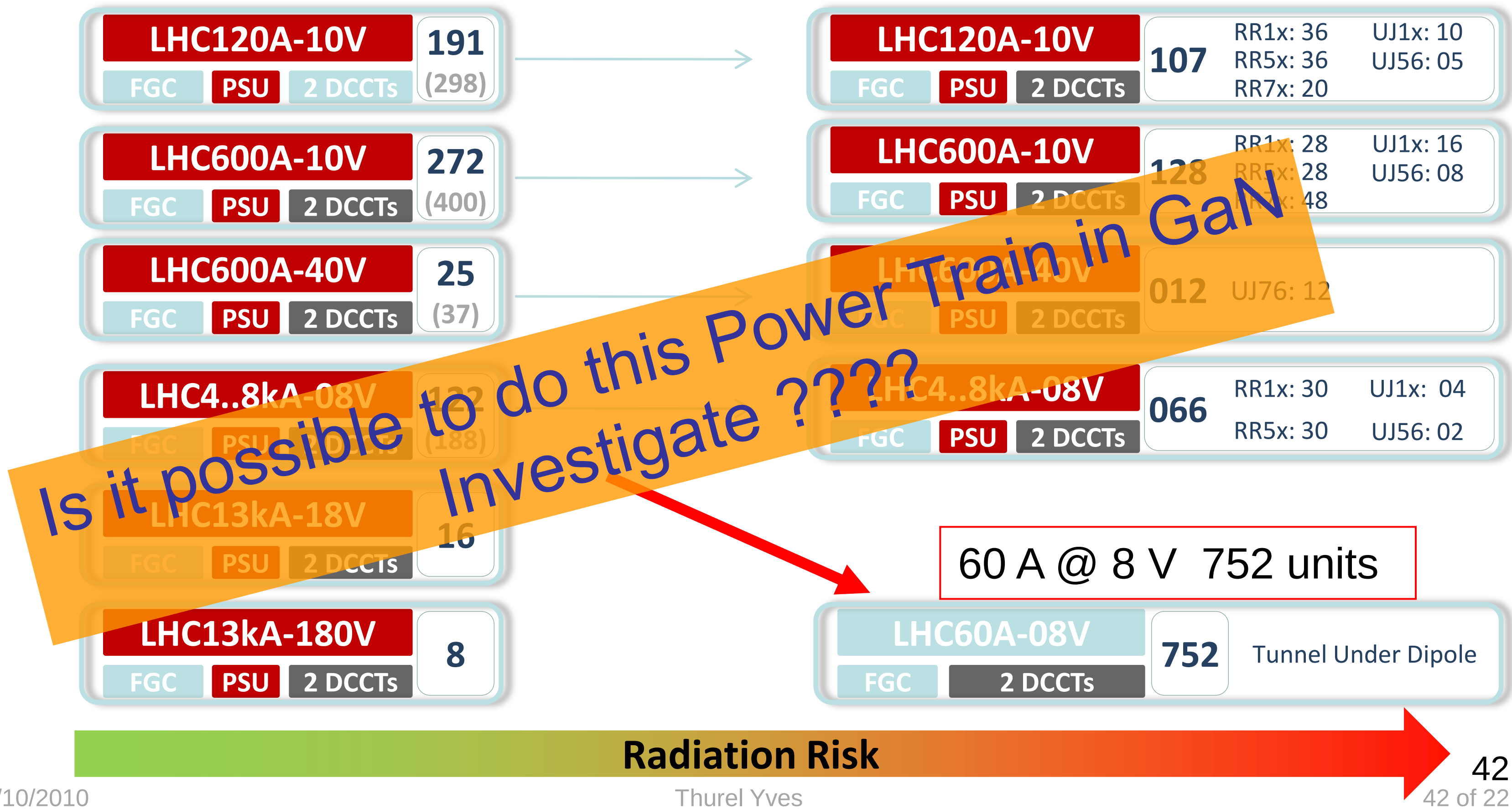
Yes = It is the EN5360

- Satellite folks are using it now
- sLHC Levels – 100 Mrads
- Use for voltage ratio = 4
- Work at Super LHC levels for Tracker
- 5.5 V in > 1.3 out
- Enpirion is still supplying these to a very large customer
- IHP foundry will make it for many years.
- Can purchase in Die form for use with Air coil

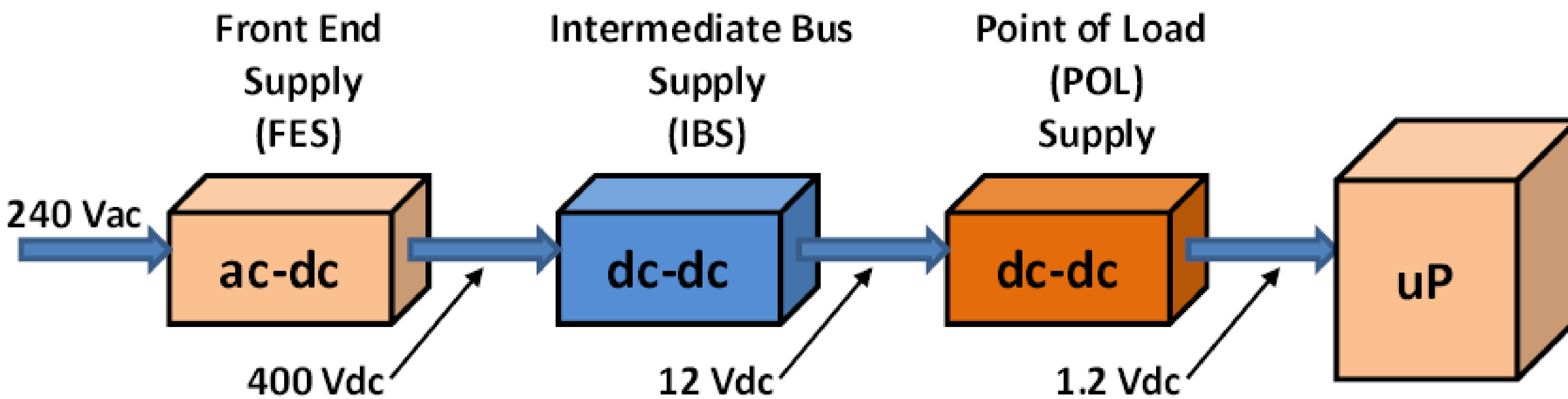
For Purchasing EN5360:
Steve Robb (908) 894 -6083 srobb@enpirion.com
Tom Howell (908) 894-6029 thowell@enpirion.com

CERN – Chamonix 2010 Report

- **LHC CONVERTERS VS RADIATION *[2010]***
  - Rad Tolerant Design *or* standard Design with low Rad sensitivity (safe components)
  - Standard Design *and* Rad sensitivity unknown (too many components, sub-assemblies...)



AC - DC Power Efficiency Challenge
by IBM September 2007



	FES	IBS	POL	Plug-to-Processor
Recent	93%	95%	88%	78%
Best Immediate	95%	98%	90%	84%
	IBM Challenge			***90%***
Needed	98%	98%	94%	***90%***

Conclusions

- The power distribution needs of HEP detectors require new solutions/technologies to meet power and environmental requirements.
- DC/DC (Buck) Converters are potential solutions for these needs.
- The environment requires that these converters operate in high radiation environments and high magnetic fields at high switching frequencies in a small size/mass package.
- Target technologies for the switches are radiation hard GaN and 0.25 μm LDMOS. High frequency controllers driving small sized nonmagnetic/air core inductors are also required.
- Many of these components have been tested and now need integration to produce a working prototype. This is the next step in our R&D program.

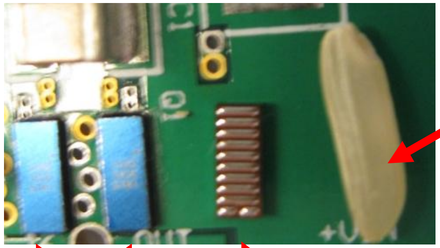
What can be achieved by this Development ?

- Current Reduction from Power Supply by DC-DC near Load
  Losses > Current^2 x Resistance

- Silicon ÷10 Current Reduction 5 Oodle > 0.5 Oodle
  CMOS converters can run @ Li Nitrogen temperature

- GaN ÷ 50 Current Reduction 5 Oodle > 0.1 Oodle
  Power Converters for Beam Line usage

Thermal Challenge



A grain of Basmati Rice
4 watts

GaN FETs
40 V 33 A 4mΩ

FET Solder side

Radiation Resistant Power Supplies with GaN ?

- ❖ Materials Journey Se .. Ge…Si…GaN
- ❖ Why Gallium Nitride. Better FOM = $R_{DS(ON)}$ X Q_G
- ❖ Enable new Capabilities ?
- ❖ High Electron Mobility
- ❖ High Frequency – 10 GHz
- ❖ X10 higher dielectric strength
- ❖ Higher Thermal Conductivity
- ❖ Majority Carrier Device – No reverse recovery
- ❖ Cost ?
- ❖ Is it easy to use? Learning curve
- ❖ End of the Silicon near?
- ❖ DC-DC Converters 48V- 1V, 400V- 48V Radiation ?
- ❖ Development 600V,1200,5000V


Working on Power Supply
Is not Glamorous
Top of the World is Cool but lonely !
Let us keep it cool with highly efficient PS
Swimming is Great at the North Pole
More Details: www.Yale.edu/FASTCAMAC click on DC-DC